

# dRICH electronics integration and SiPM

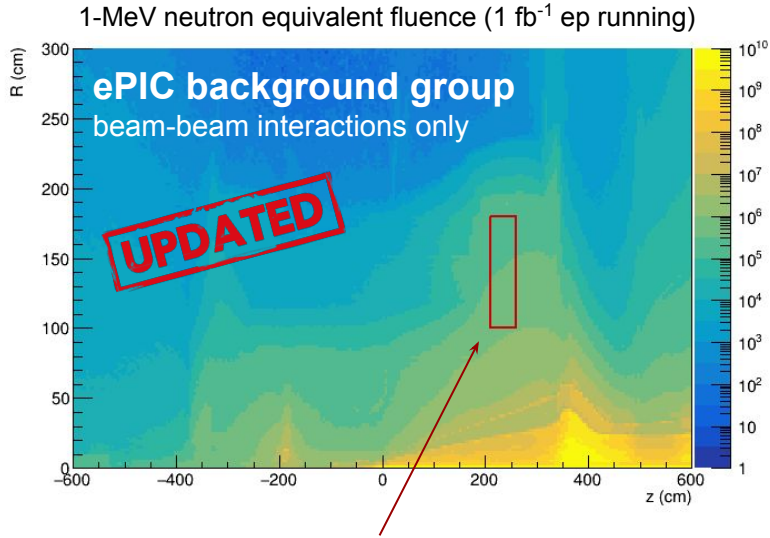
**Roberto Preghenella**

INFN Bologna

activities involving BO, CS, CT, FE, SA, TO

stato R&D

# Neutron fluxes at the dRICH photosensor surface



location of dRICH photosensors  
 mean fluence:  $3.9 \cdot 10^5 \text{ neq} / \text{cm}^2 / \text{fb}^{-1}$   
 max fluence:  $9.2 \cdot 10^5 \text{ neq} / \text{cm}^2 / \text{fb}^{-1}$

- radiation level is moderate

**assume fluence:  $\sim 10^7 \text{ neq} / \text{cm}^2 / \text{fb}^{-1}$**   
 conservatively assume max fluence and 10x safety factor

Most of the key Physics goals defined by the NAS require an integrated luminosity of  $10 \text{ fb}^{-1}$  per center of mass energy and polarization setting

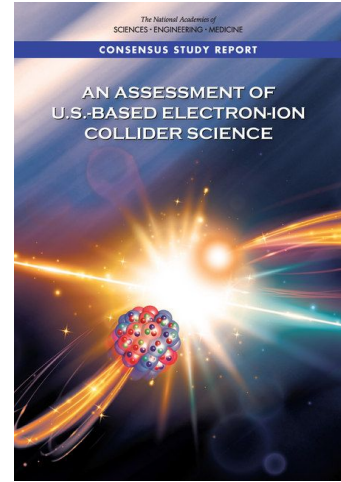
The nucleon imaging programme is more luminosity hungry and **requires  $100 \text{ fb}^{-1}$  per center of mass energy and polarization setting**

in 10-12 years the EIC will accumulate  $1000 \text{ fb}^{-1}$  integrated  $\mathcal{L}$  corresponding to an integrated fluence of  $\sim 10^{10} \text{ n}_{\text{eq}} / \text{cm}^2$

**study the SiPM usability for single-photon Cherenkov imaging applications in moderate radiation environment**

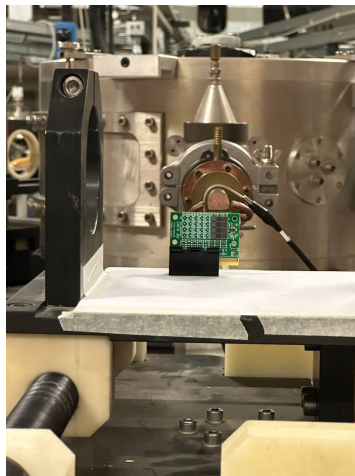
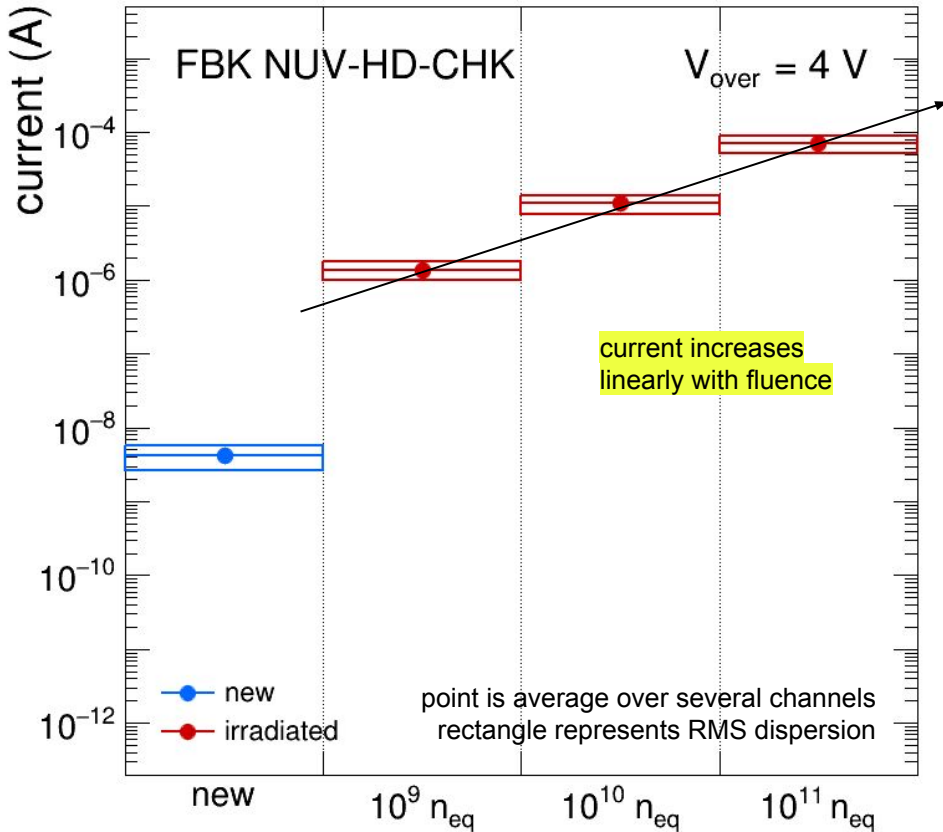
→ radiation damage studied in steps of radiation load

- |  |   |
|--|---|
| $10^9$ 1-MeV $\text{n}_{\text{eq}} / \text{cm}^2$    | <i>most of the key physics topics</i>           |
| $10^{10}$ 1-MeV $\text{n}_{\text{eq}} / \text{cm}^2$ | <i>should cover most demanding measurements</i> |
| $10^{11}$ 1-MeV $\text{n}_{\text{eq}} / \text{cm}^2$ | <i>might never be reached</i>                   |



# Studies of radiation damage on SiPM

in 2023 done also neutron irradiation and variable proton energy irradiation



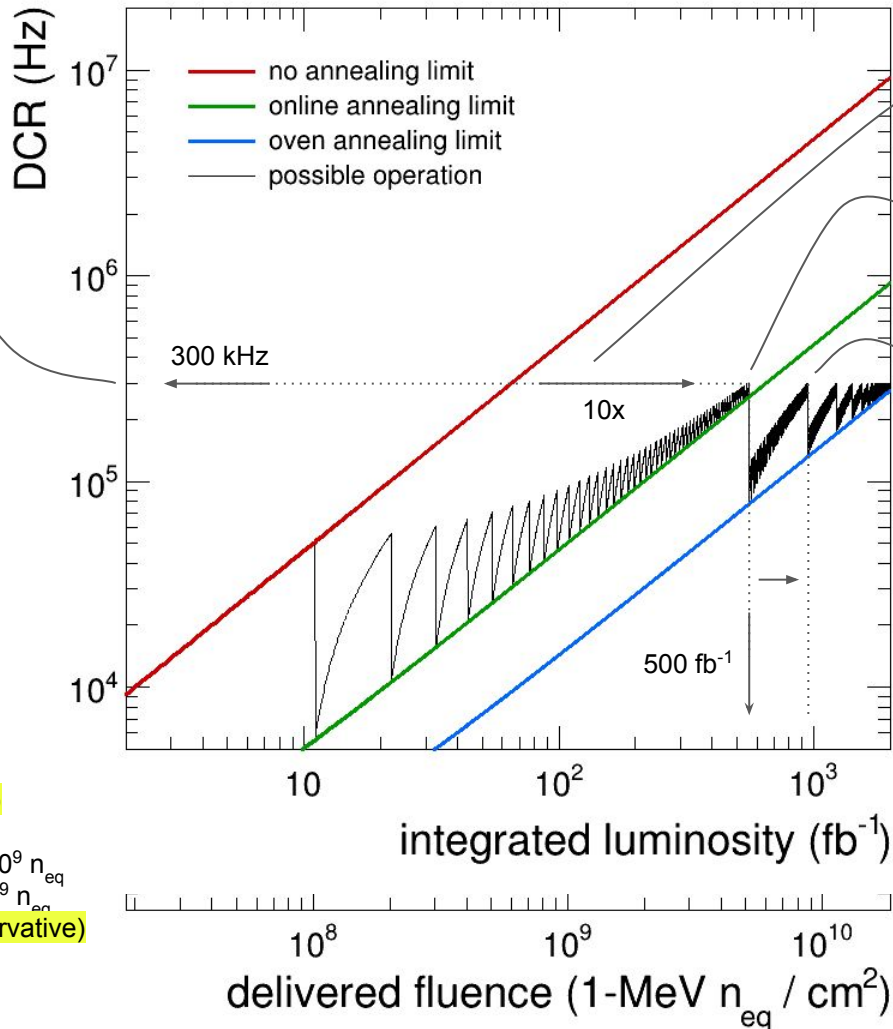
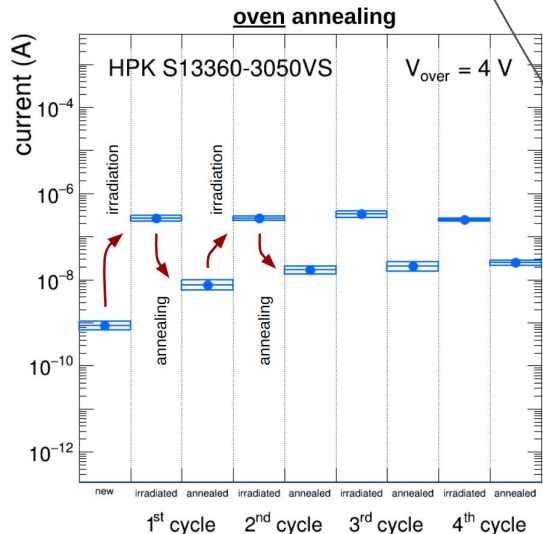
all results are reported at T = -30 C



# Ageing model

Hamamatsu S131360-3050 @  $V_{over} = 4\text{ V}$ ,  $T = -30\text{ C}$

max acceptable DCR for  
Physics performance  
~ 10 noise hits / sector within 500 ps



online annealing  
extends SiPM  
lifetime by ~ 10x

more aggressive  
annealing needed here  
might need to unmount SiPM (oven)

up to  $1000\text{ fb}^{-1}$  with only  
one oven annealing cycle  
optimisation of online annealing  
protocol could reach beyond that

these predictions are according to  
present knowledge / tested solutions

there are more handles to  
further mitigate DCR

lower  $V_{over}$ , 3V  
lower T operation -40 C or below

## model input from R&D measurements (up to 2022)

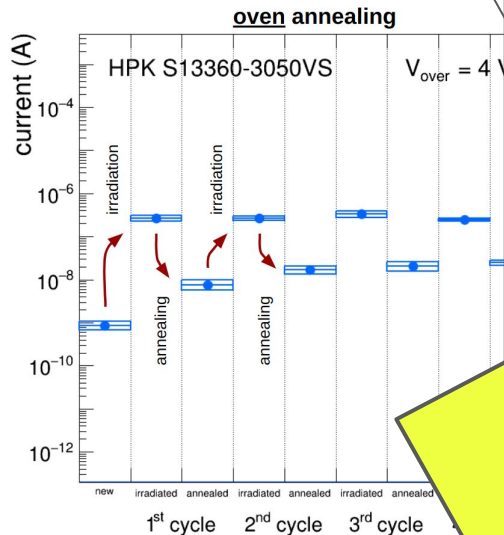
- DCR increase:  $500\text{ kHz}/10^9 n_{eq}$
- residual DCR (online annealing):  $50\text{ kHz}/10^9 n_{eq}$
- residual DCR (oven annealing):  $15\text{ kHz}/10^9 n_{eq}$

## 1-MeV $n_{eq}$ fluence from background group (conservative)

- $9 \times 10^6 n_{eq} / \text{fb}^{-1}$
- includes 10x safety factor

# Ageing model

max acceptable DCR for  
Physics performance  
~ 10 noise hits / sector within 500 ps



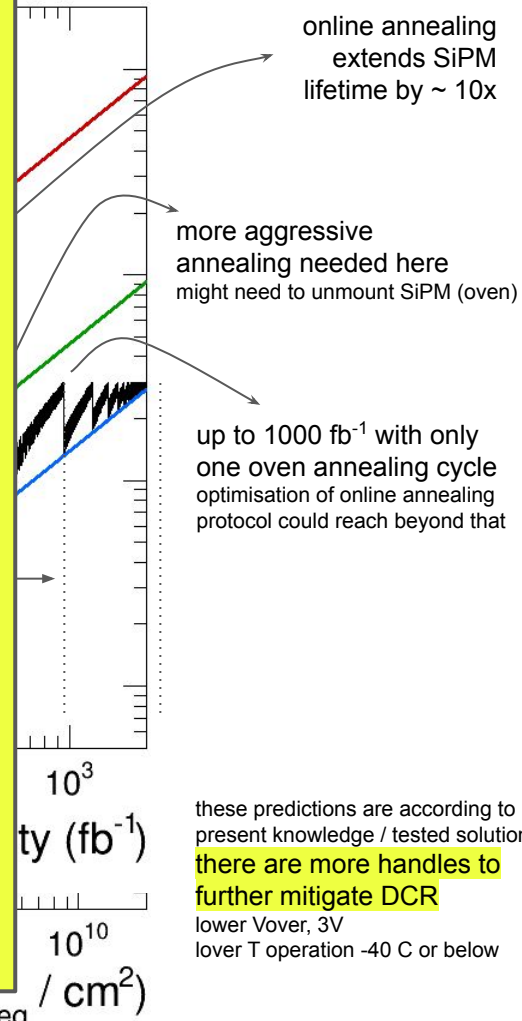
**important to continue irradiation studies in 2024 towards the preparation of the TDR (this is also synergy with DRD4)**

- they are extremely valuable to refine our understanding of SiPM aging at the EIC
- they are fundamental to optimise and engineer the potential of annealing and damage recovery strategies

**funds requested to support continuation of proton (TIFPA) irradiation and neutron (LNL) irradiation campaigns in 2024 (BO, CS, CT, FE, SA)**

- we did not yet evaluate the impact of high-energy photons (X and gammas) irradiation

**funds requested for an irradiation campaign at the CERN-GIF facility (BO, CS, CT, FE, SA)**



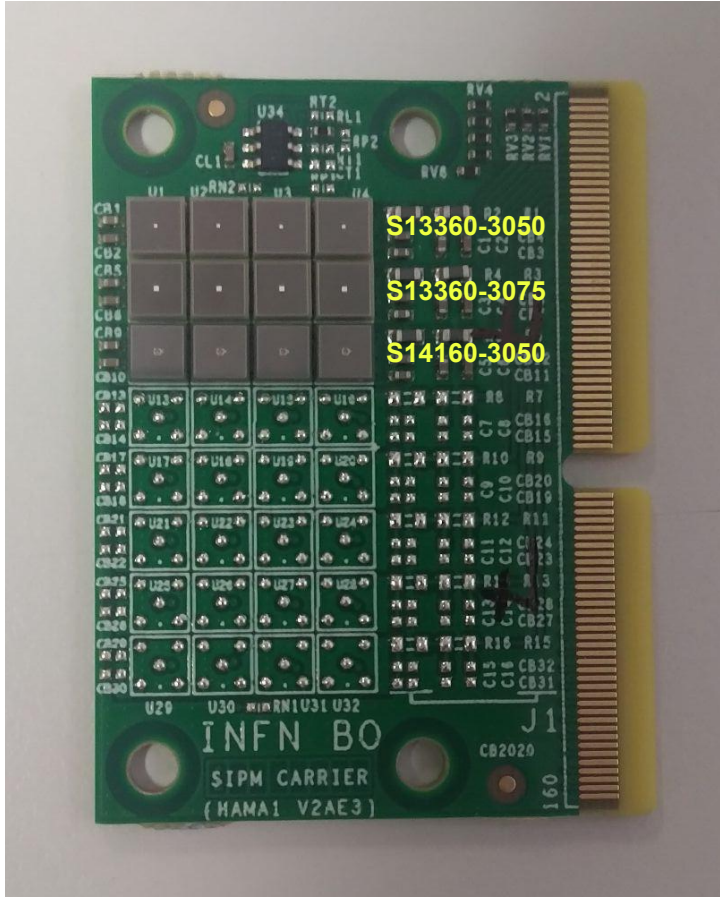
model input from R&D measurements (up to)

- DCR increase: 500 kHz/ $10^9 n_{eq}$
- residual DCR (online annealing): 50
- residual DCR (oven annealing): 15 k

1-MeV  $n_{eq}$  fluence from background group (

- $9 \cdot 10^6 n_{eq} / fb^{-1}$
- includes 10x safety factor

# New SiPM custom boards for characterisation (2023 program)



- **35 new boards have been produced**
  - same design from 2020
  - populate only 3 rows
    - 4 sensors, for minimal statistical sample
  - sensors from Hamamatsu
    - S13360-3050
    - S13360-3075
    - S14160-3050
  - replaced 50  $\Omega$  RC resistors with ferrite beads
    - allow to perform annealing
    - same components used for prototype
- **irradiation studies**
  - proton energy scan (TIFPA)
    - irradiation done in June 2023
  - neutron damage (LNL)
    - irradiation to done in August 2023
  - more proton irradiation (TIFPA)
    - November - December 2023
- **annealing studies**
  - online annealing
    - forward and reverse bias
  - detailed studies of annealing techniques
    - time and temperature dependence
    - comparison of different techniques

these boards will suffice to cover 2024 irradiation campaigns

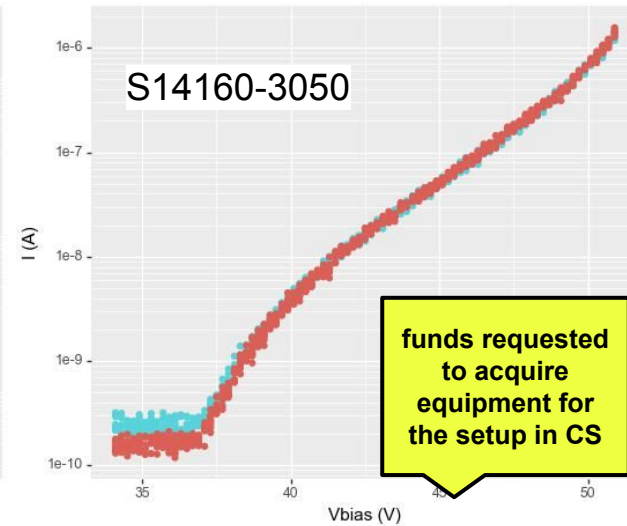
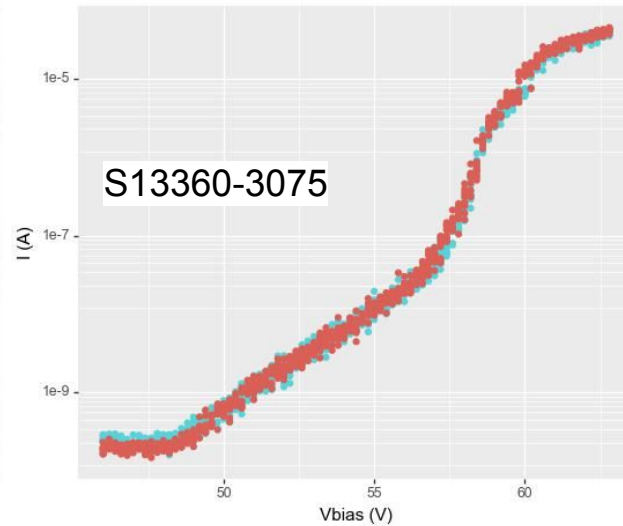
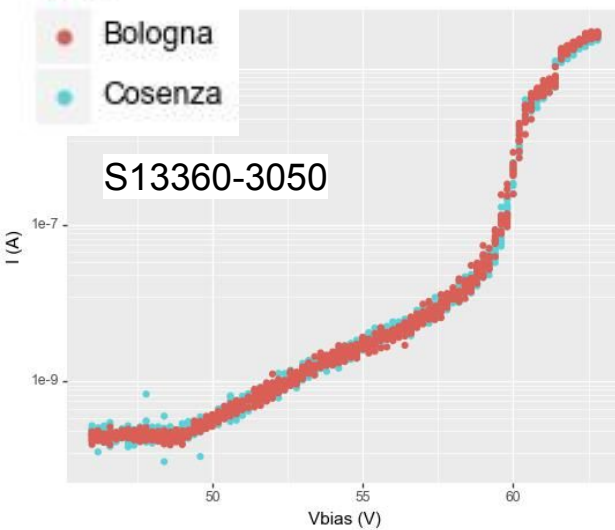
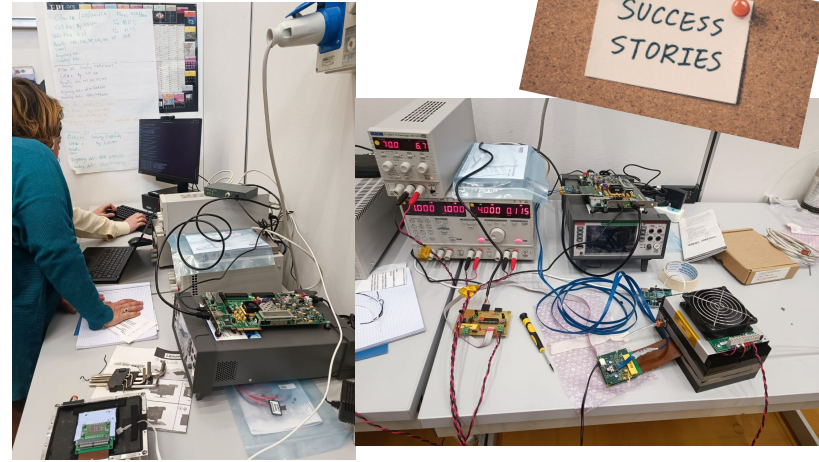
# Characterisation setup in Cosenza

IV characteristics of 3 different SiPM types compared measured both in Bologna and Cosenza setups

- Bologna uses climatic chamber
- Cosenza uses AirBox air-cooled Peltier setup

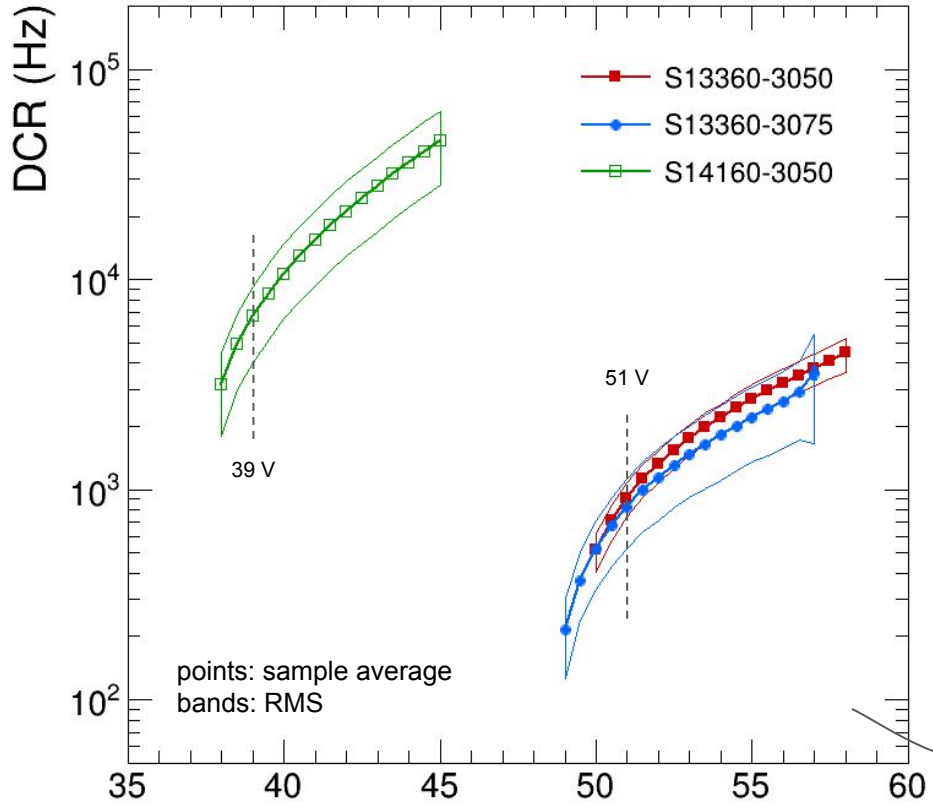
the results are nicely compatible between the two setups

**Cosenza setup is up and running to efficiently contribute to SiPM R&D and characterisation**

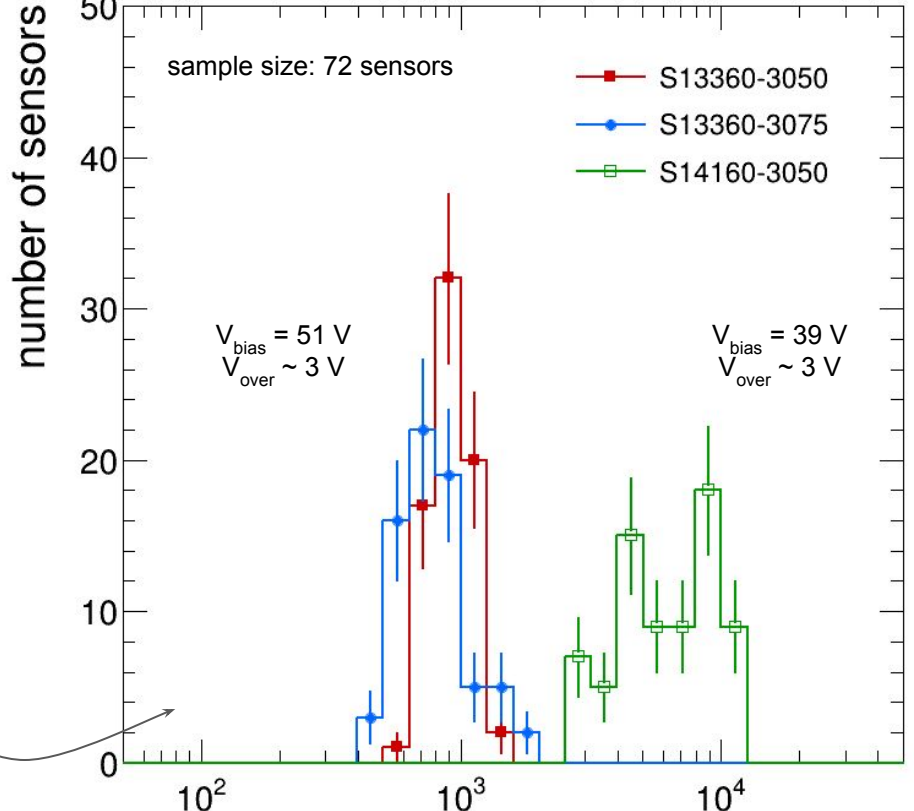


# Characterisation of new SiPM boards

new sensors before irradiation ( $V_{bias}$  dependence)



new sensors before irradiation (sample at fixed  $V_{bias}$ )



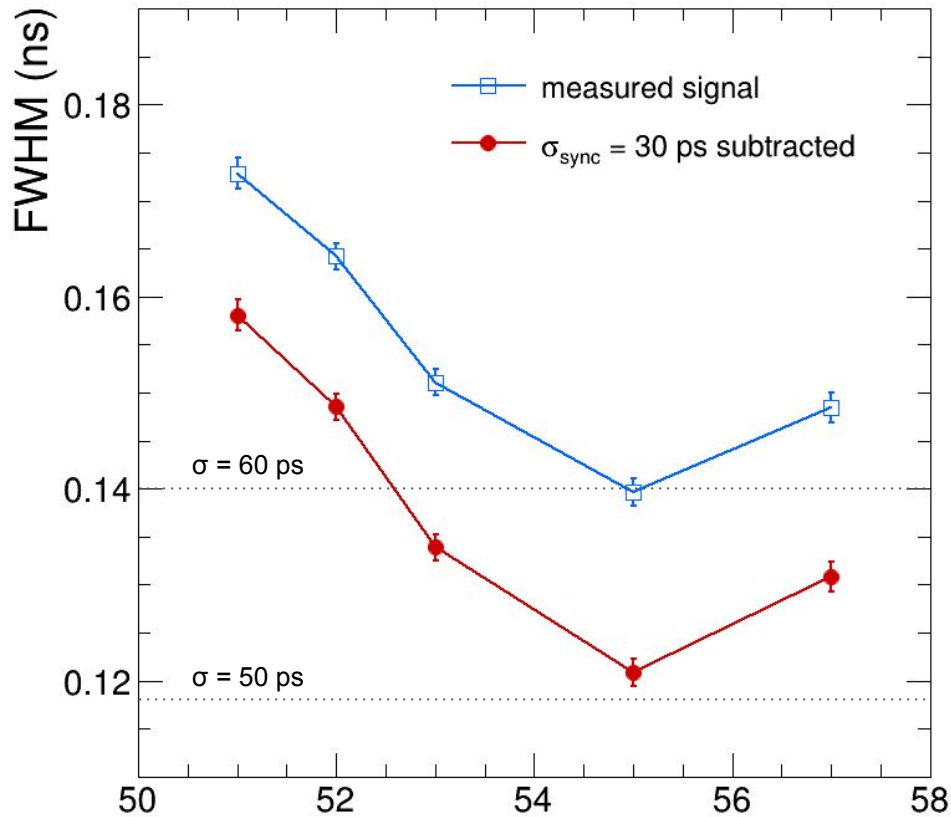
S13360-3075 have lowest DCR at  $V_{over} = 3\text{ V}$  and at same time they have high PDE (50%)

bias voltage (V)

DCR (Hz)

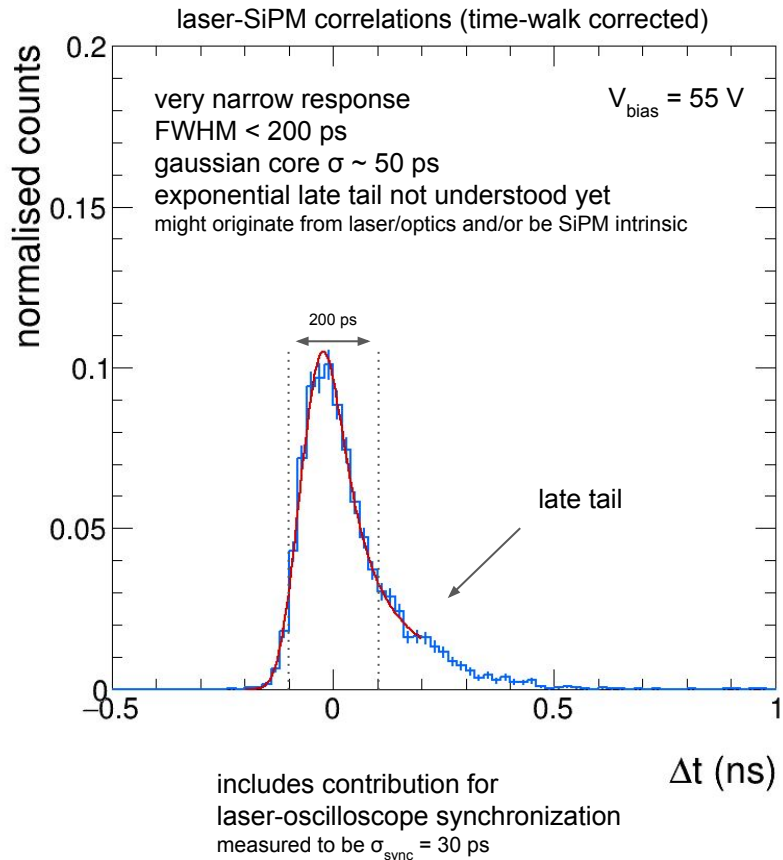


# Laser timing measurements with oscilloscope



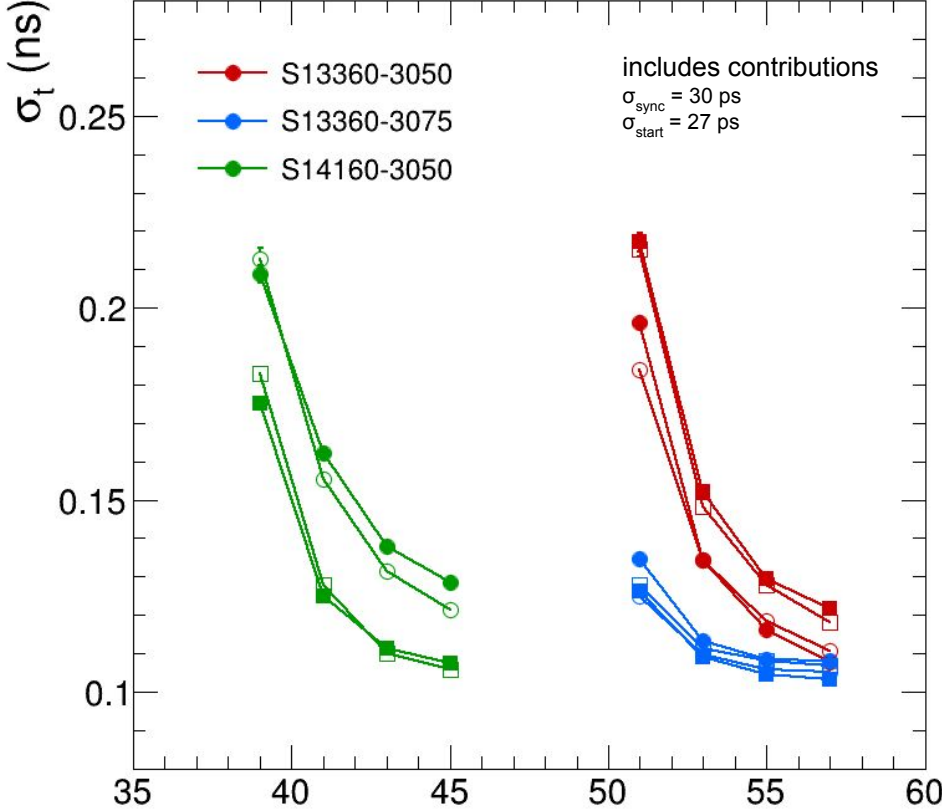
approaching  $\sigma_t = 50$  ps time resolution  
 will soon measure effect of radiation damage on  $\sigma_t$

bias voltage (V)

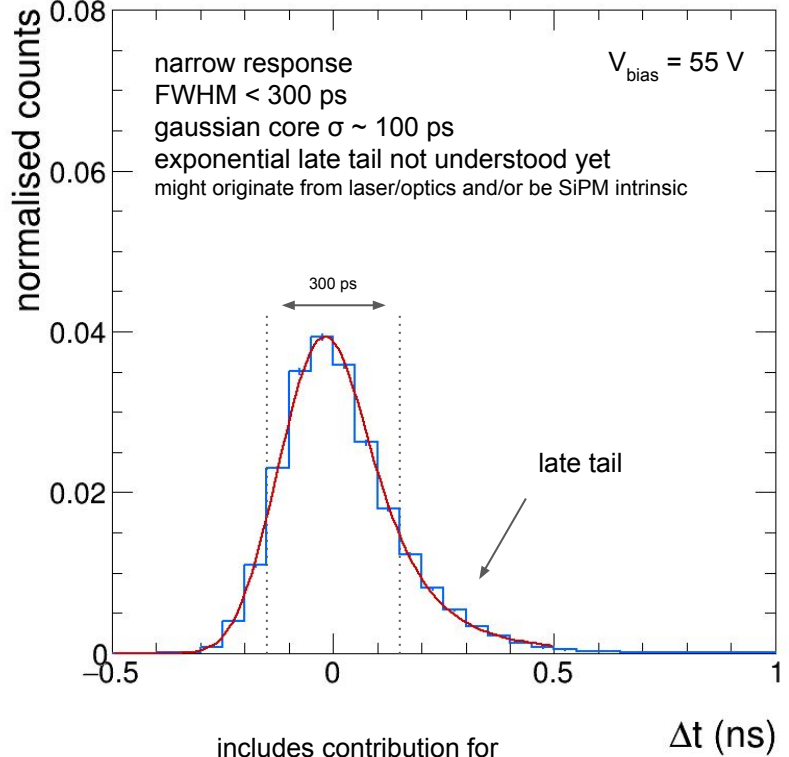


# Laser timing measurements with ALCOR

standard ALCOR front-end bias configuration



laser-SiPM correlations (time-walk corrected)



includes contribution for laser-ALCOR synchronization measured to be  $\sigma_{sync} = 30$  ps and reference time resolution measured to be  $\sigma_{start} = 27$  ps

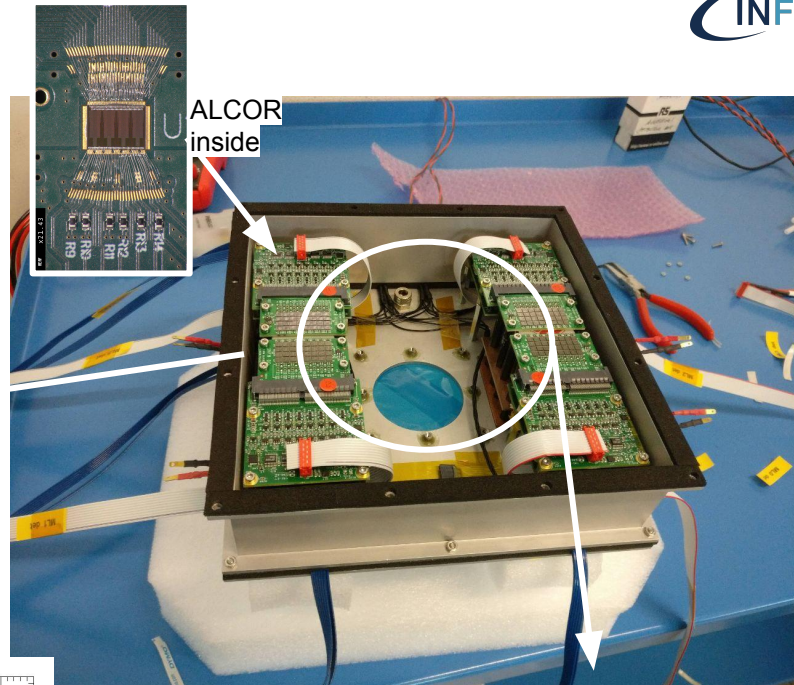
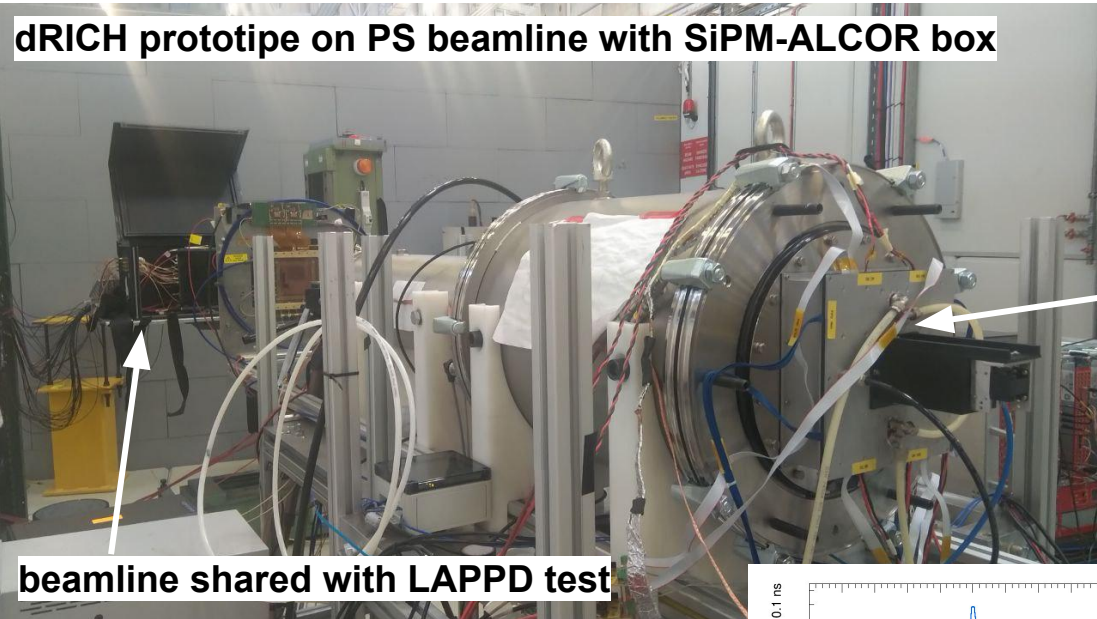
better time resolution with 75  $\mu$ m SPADs comfortably below  $\sigma_t = 150$  ps also at low  $V_{bias}$

bias voltage (V)



# 2022 test beam at CERN-PS

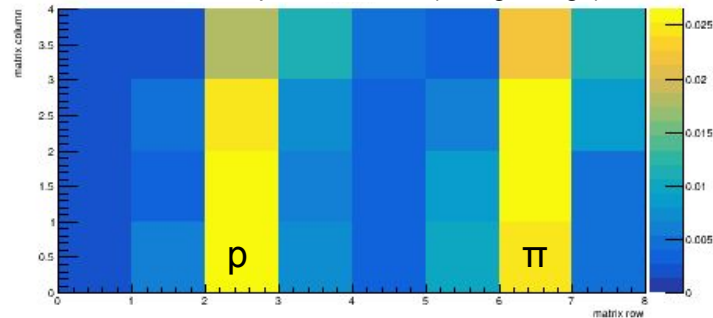
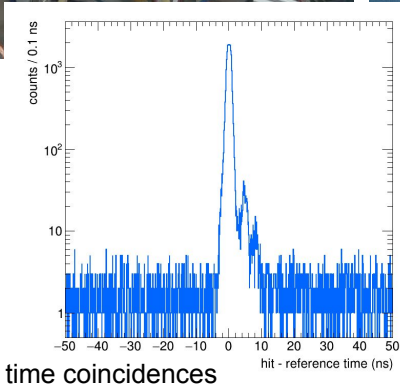
dRICH prototipe on PS beamline with SiPM-ALCOR box



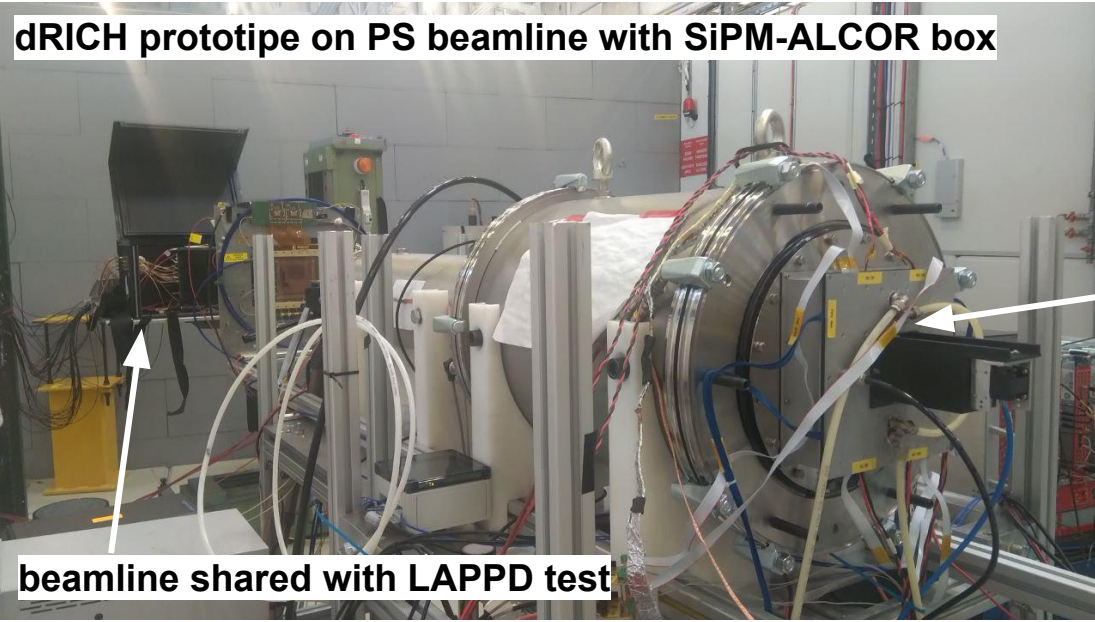
8 GeV positive beam (aerogel rings)

beamline shared with LAPPD test

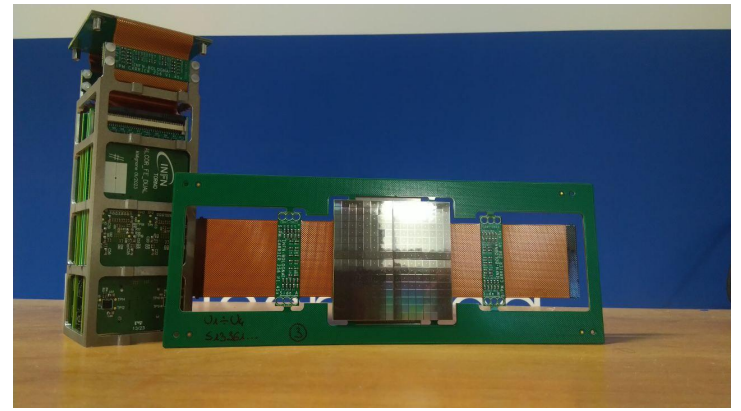
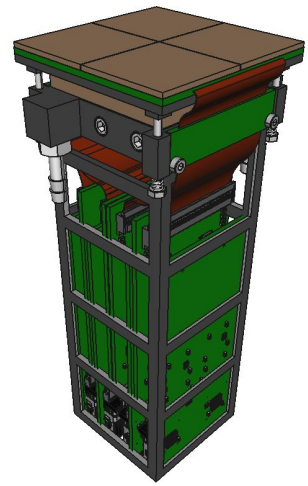
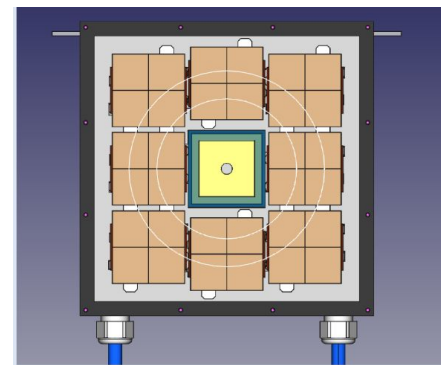
**successful operation of SiPM**  
irradiated (with protons up to  $10^{10}$ )  
 and annealed (in oven at 150 C)



# New detector plane for 2023 beam tests



prototype EIC-driven readout unit and readout box



**a few prototype photodetector units**

will be assembled and tested in September

before mounting them on the dRICH detector prototype for the beam test

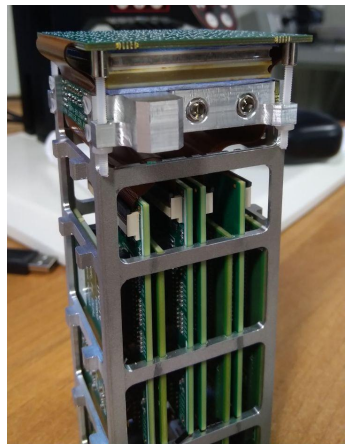
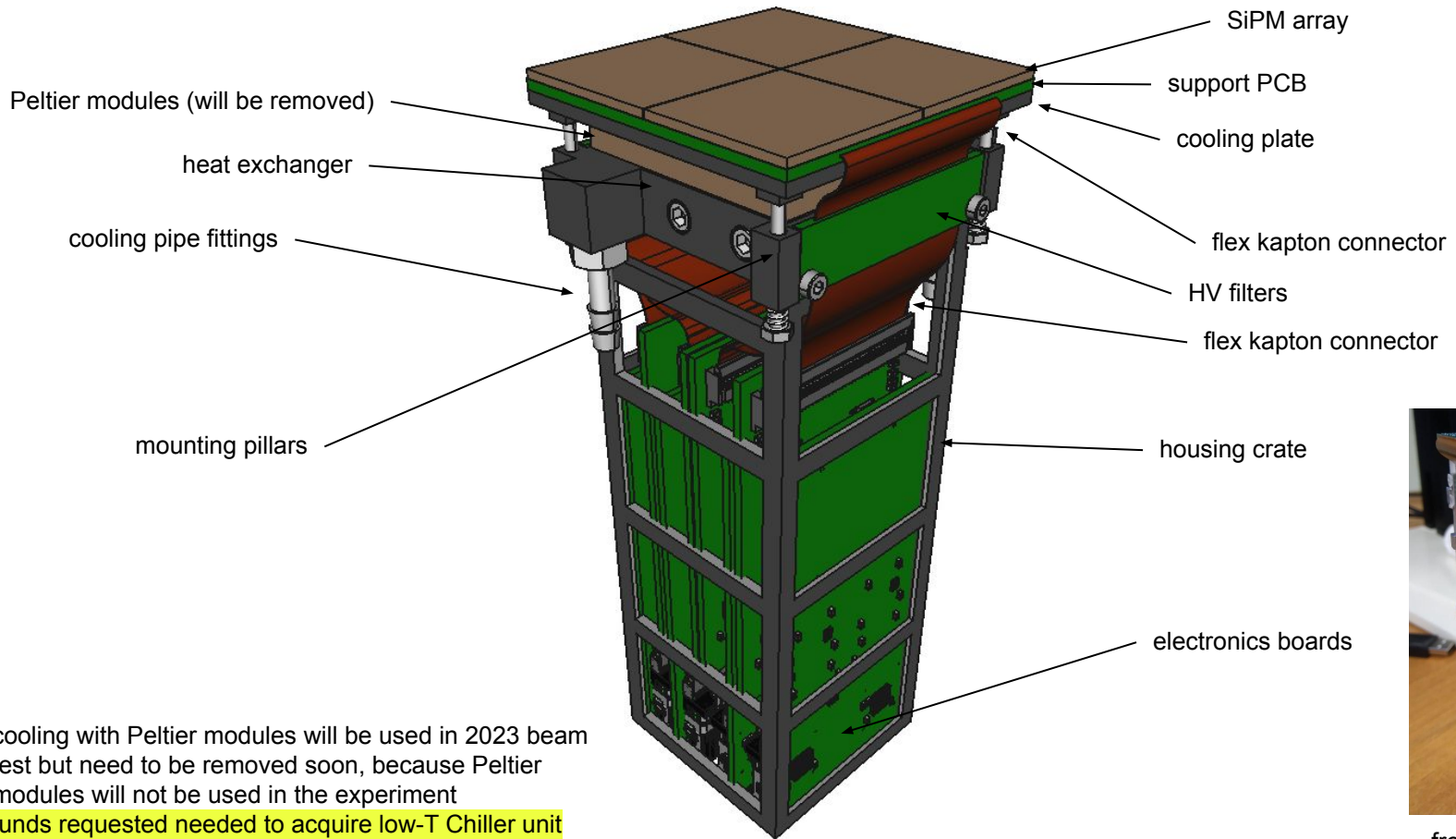
prototype PDU

# dRICH SiPM prototype photodetector unit (PDU)

- **large-area EIC-driven SiPM optical readout for the dRICH prototype**
  - based on ALCOR readout
  - milestone deadlines (eRD102 project)
    - realisation: April 2023
    - beam test: October 2023
- **SiPM sensors and layout**
  - each readout unit comprises of
    - 4 Hamamatsu 8x8 matrices
    - 256 channels
  - ~ 52 x 52 mm<sup>2</sup> area
- **design with layout as close as possible to needs for final experiment**
  - critical engineering exercise in view of TDR
  - place cooling and electronics on the back of the sensors
- **use as much as possible of current electronics architecture**
  - no manpower capacity to develop new FPGA board this year
  - no manpower capacity to develop new firmware this year
  - use ALCORv2 (32 channels)
- **design new electronics boards to fit the new layout configuration**
  - possibly with the same features, if all needed



# Prototype photodetector unit (PDU)

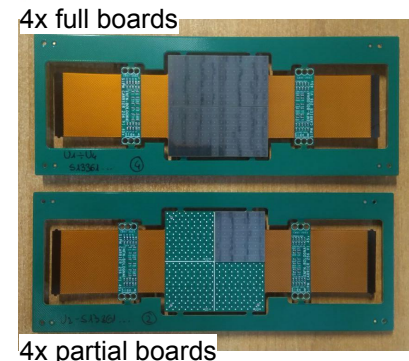
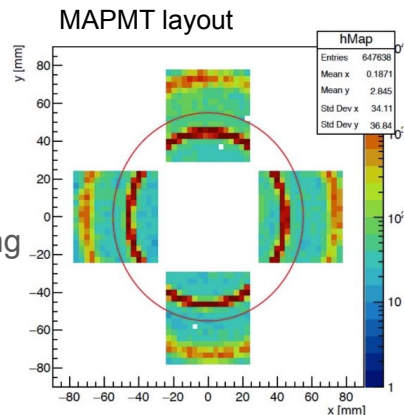


from design to assembly

cooling with Peltier modules will be used in 2023 beam test but need to be removed soon, because Peltier modules will not be used in the experiment  
funds requested needed to acquire low-T Chiller unit  
prototype PDU design done to allow this change in 2024

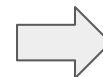
# Prototype PDU status

- **acquired 20x Hamamatsu 8x8 SiPM matrix arrays**
  - eRD102 funds
  - sufficient to populate 4 full PDUs + 1 spare
  - map MAPMT readout layout
  - for 2023 beam test we eventually decided to optimise for testing
    - populated 4 full carrier boards
    - populated 4 partial carrier boards
- **produced electronic boards needed, with spares**
  - 1x carrier board / PDU
  - 4x adapter boards / PDU
  - 4x ALCOR boards / PDU
  - 8x ALCOR chips / PDU
  - 4x Masterlogic boards / PDU
- **acquired ancillary material and boards**
  - many cables
  - Peltier modules
  - FPGA boards
  - clock distribution
  - ...
- **produced mechanical pieces for 10x PDUs**
  - cooling hardware
  - mini-crate for electronics
- **extend the readout to cover the full area in 2024**
  - INFN fund requests to acquire more SiPM and electronics → **produce 4 PDUs + 1 spare**



SiPM layout (2023)

U2	U4	U2	U4	U2	U4
U1	U3	U1	U3	U1	U3
U2	U4			U2	U4
U1	U3			U1	U3
U2	U4	U2	U4	U2	U4
U1	U3	U1	U3	U1	U3

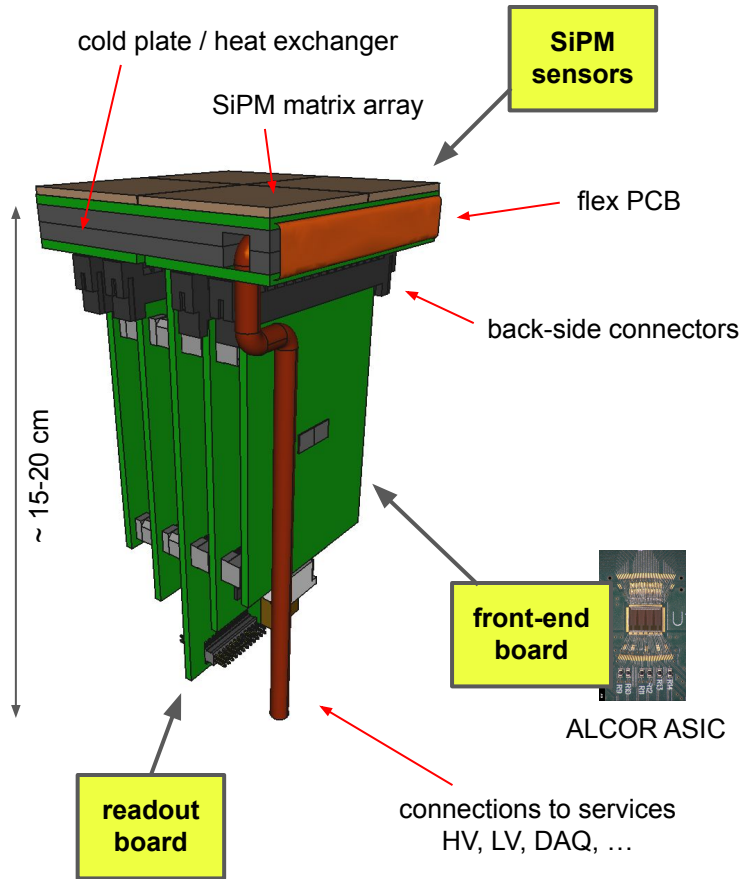


SiPM layout (2024)

U2	U4	U2	U4	U2	U4
U1	U3	U1	U3	U1	U3
U2	U4			U2	U4
U1	U3			U1	U3
U2	U4	U2	U4	U2	U4
U1	U3	U1	U3	U1	U3

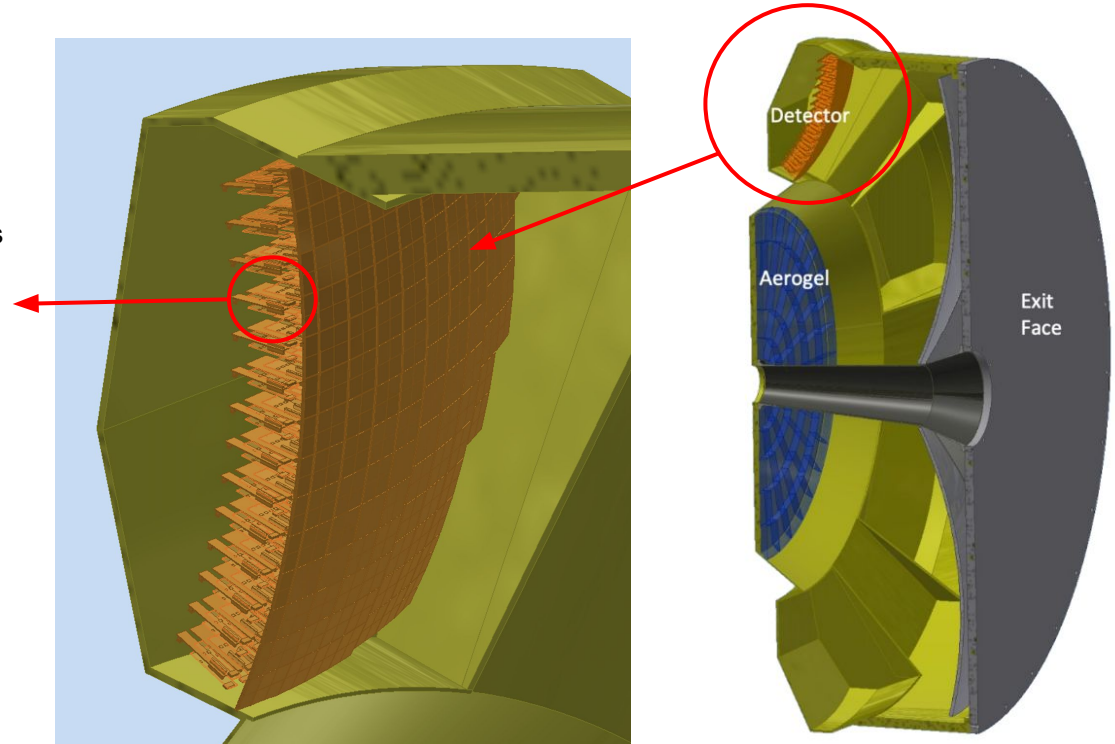
# Photodetector unit

## conceptual design of final layout



## plans for realisation of the final prototype units

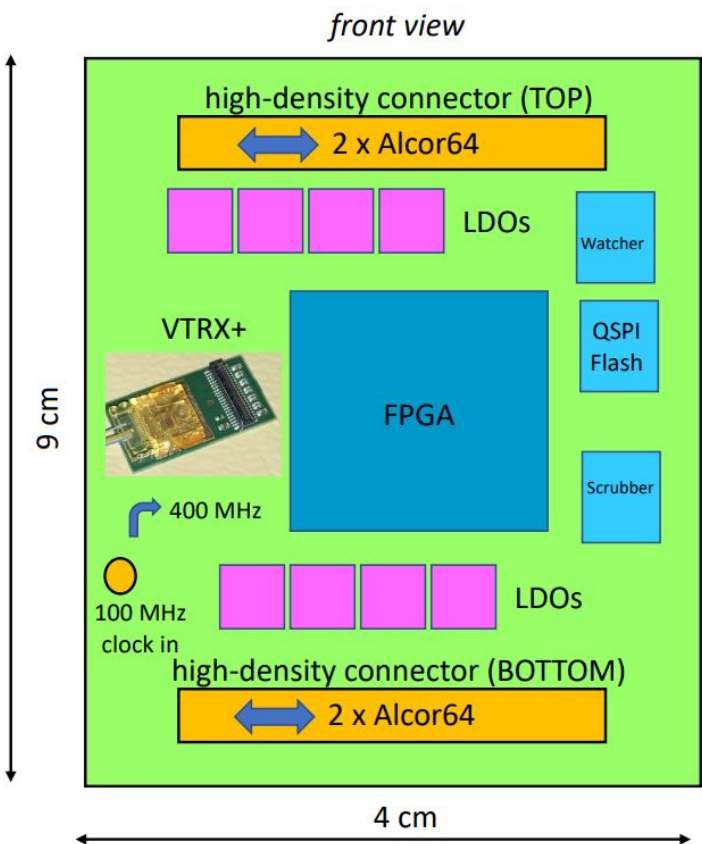
- 2024: readout board (RDO) realisation and test beam
- 2024: front-end board (FEB) with ALCOR-v3 (64ch BGA)
- 2025: final SiPM carrier realisation and test beam





# Readout board

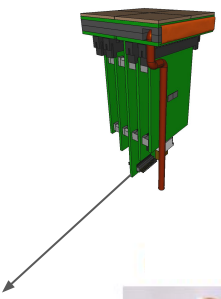
conceptual design of RDO architecture



time to start developing custom readout boards for 2024 beam tests and TDR

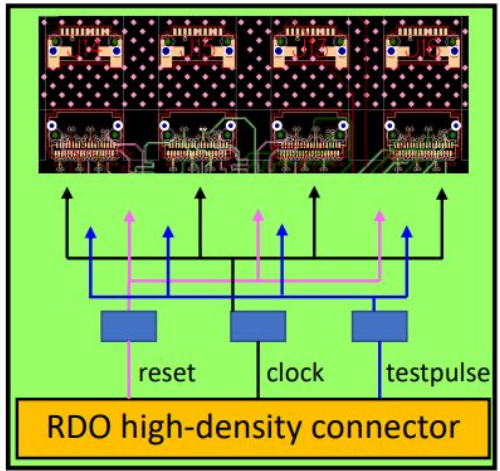
2024: design and develop 10x RDO boards

- close to the final RDO design and PDU layout
- with the capability to also serve current electronics



**current breakout board**  
already existing (2023 test beam)

connects current ALCOR FireFly electronics to FMC connector of commercial FPGA board



**new breakout board**  
to be made in 2024

needed to connect current ALCOR FireFly electronics to RDO high-density connector

INFN funds requested for realisation of 10x RDO boards, 10x new breakout boards, acquire FireFly cables and data aggregator DAQ system (Virtex FPGA + server)

# The great management plan towards construction

	Year Quarter	2023				2024				2025			
		Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4
<b>Milestone</b>	TDR								x				
	test beam				x				x	x			x
<b>sensors</b>	SiPM carrier v2	design	order	ready		ready	ready	ready	ready				
	SiPM carrier vF								design	order	ready		
<b>front-end</b>	ALCOR v2	order	ready	ready	ready	ready	ready	ready	ready				
	ALCOR-FE v2		ready	ready	ready	ready	ready	ready	ready				
	ADAPTER v2			ready	ready	ready	ready	ready	ready				
	MasterLogic v2	design	order	ready	ready	ready	ready	ready	ready				
	ALCOR v64			design	design	design	design	order	order	ready	ready		
	FEB v64			design	design	design	design	order	order	ready	ready	ready	ready
	packaging			design	design	design	design	order	order	ready	ready	ready	ready
	ALCOR vF							design	design		order	order	ready
FEB vF									design	order	ready	ready	
<b>readout</b>	KC705	ready	ready	ready	ready	ready	ready	ready	ready				
	RDO v2				design	design	design	order	ready	ready			
	breakout boards v2				design	design	design	order	ready				
	VC709							order	ready	order	ready	ready	ready
	felix									order	ready	ready	ready
RDO vF									design	order	ready	ready	



important milestones

**TDR in 2024:**  
have very high design maturity

**beam tests in 2025:**  
test the final layout and the electronics

# attività e richieste 2024

# Summary

- **sviluppo prototipi readout board RDO**
  - Sviluppo e produzione di 10 schede prototipo Readout Board dRICH RDO
  - Produzione e assemblaggio di 10x schede JC23-225 Breakout board
  - Cavi interfaccia scheda-scheda SAMTEC FireFly ad alta velocità
  - KIT SVILUPPO, VIRTEX-7 FPGA
  - Server con processore aggiuntivo e 32 GB di RAM per readout RDO
- **realizzazione nuovi prototipi di photodetector units PDU**
  - Acquisto componenti, cavi e materiale per l'assemblaggio e test dei prototipi
  - Produzione e assemblaggio SiPM carrier boards per PDU prototipo
  - Matrici 8x8 SiPM Hamamatsu S13360 per prototipo dRICH
  - produzione e assemblaggio di schede ADAPTER-64
  - produzione e assemblaggio di schede ALCOR-DUAL
  - produzione e assemblaggio di schede MasterLogic-v2
- **strumentazione ed equipaggiamento per test in laboratorio e su fascio**
  - Sistema chiller con liquido di circolazione e tubazioni coibentate
  - Oscilloscopio da banco/portatile 4 ch. analogici, 16 ch. digitali, 200MHz
  - Picoamperometro da banco Keithley 6487/E, 20mA ca, Cert. LAT
  - ThinkCentre M75T Desktop con monitor e scheda di rete aggiuntiva
  - Essiccatore aria SMC IDFA11E-23
  - Compressore d'aria da laboratorio
  - Gruppo di continuità
- **collaborazione e attività di R&D su SiPM (sinergie DRD4)**
  - missioni per collaborazione tra le sezioni di BO, CS, CT, FE, SA
  - spese per fascio presso il Centro di ProtonTerapia di Trento
  - missioni per test di irraggiamento presso il TIFPA, Legnaro e il CERN



# SiPM cooling for low-temperature operation ( $-30\text{ }^{\circ}\text{C}$ or lower)



external chiller with fluid recirculation (ie. siliconic oil)  
 the chiller here one is just a commercial example  
**cooling and heating capacity**  
 could use heating capability for annealing? must be demonstrated to be feasible  
 cooling capacity at  $-40\text{ }^{\circ}\text{C}$  is large (1.5 kW)

**huber**

° General & Temperature Control

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Temperature range  $-55...250\text{ }^{\circ}\text{C}$

Temperature stability  $\pm 0,01\text{ K}$

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⚙️ Heating / cooling capacity

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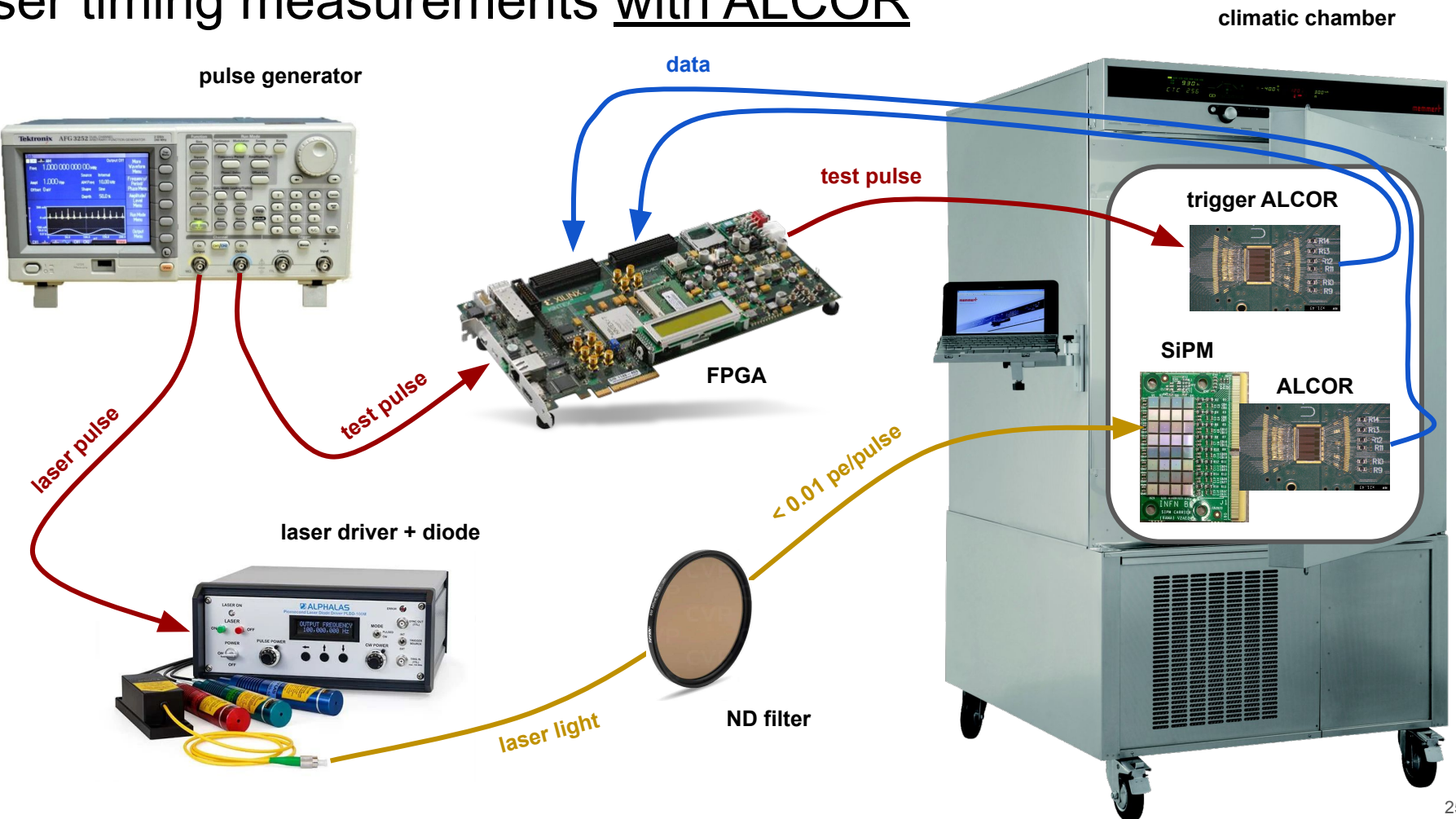
Heating capacity 6 kW

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Cooling capacity

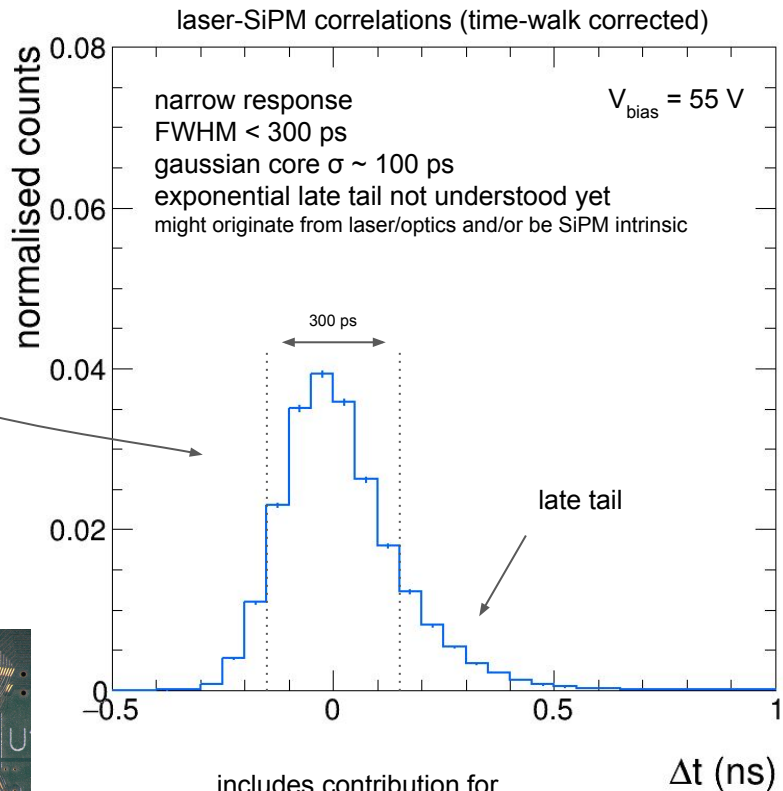
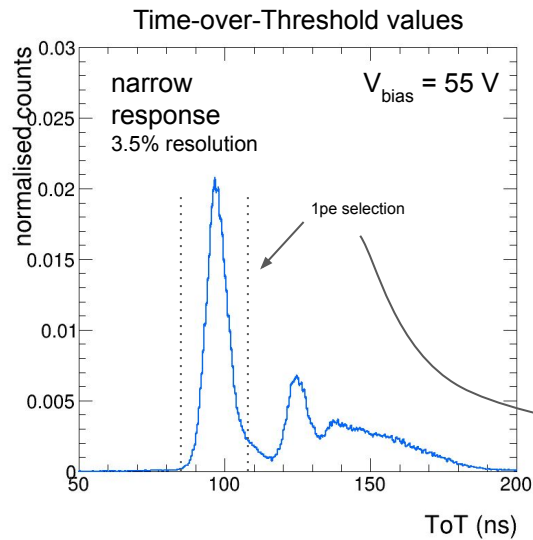
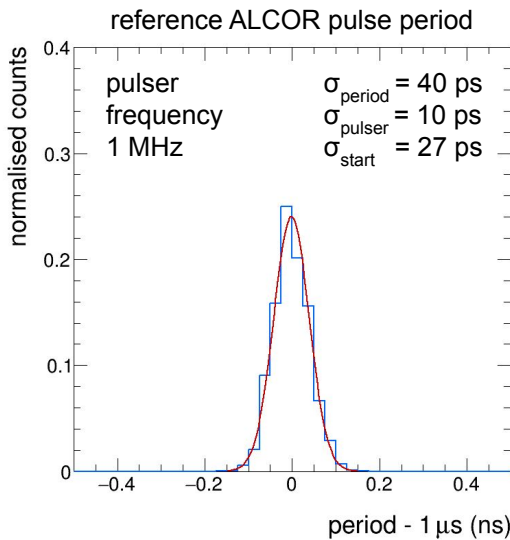
	250	200	100	20	0	-20	-40	-50	$^{\circ}\text{C}$
	6	6	6	6	6	4,2	1,5	0,65	kW

# Laser timing measurements with ALCOR





# Laser timing measurements with ALCOR



## laser-SiPM signal synchronisation by sending test pulse to reference ALCOR

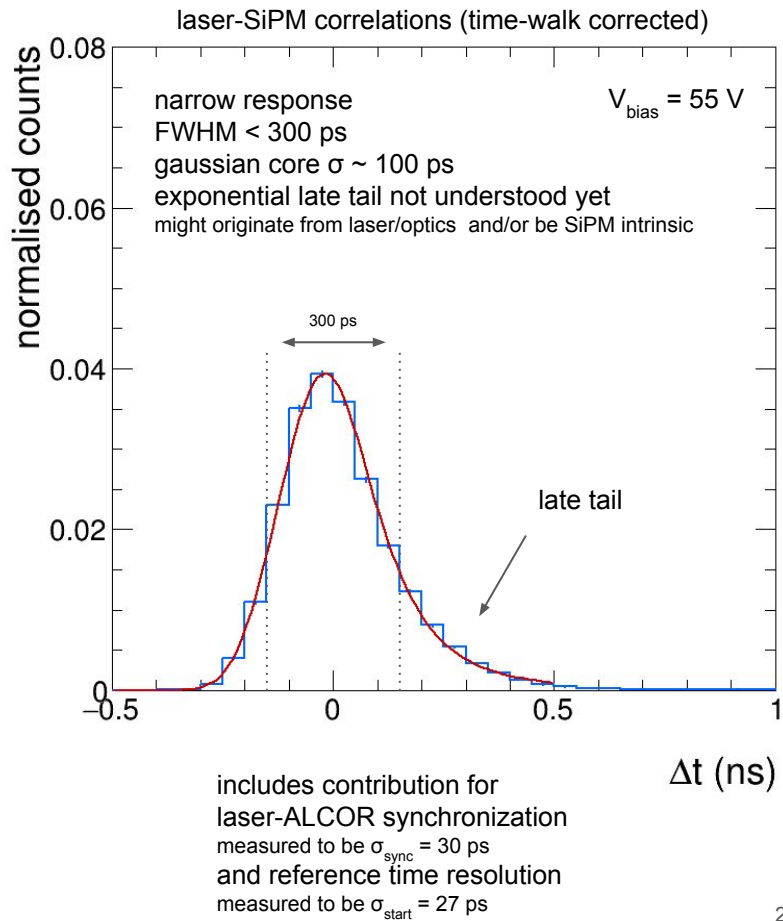
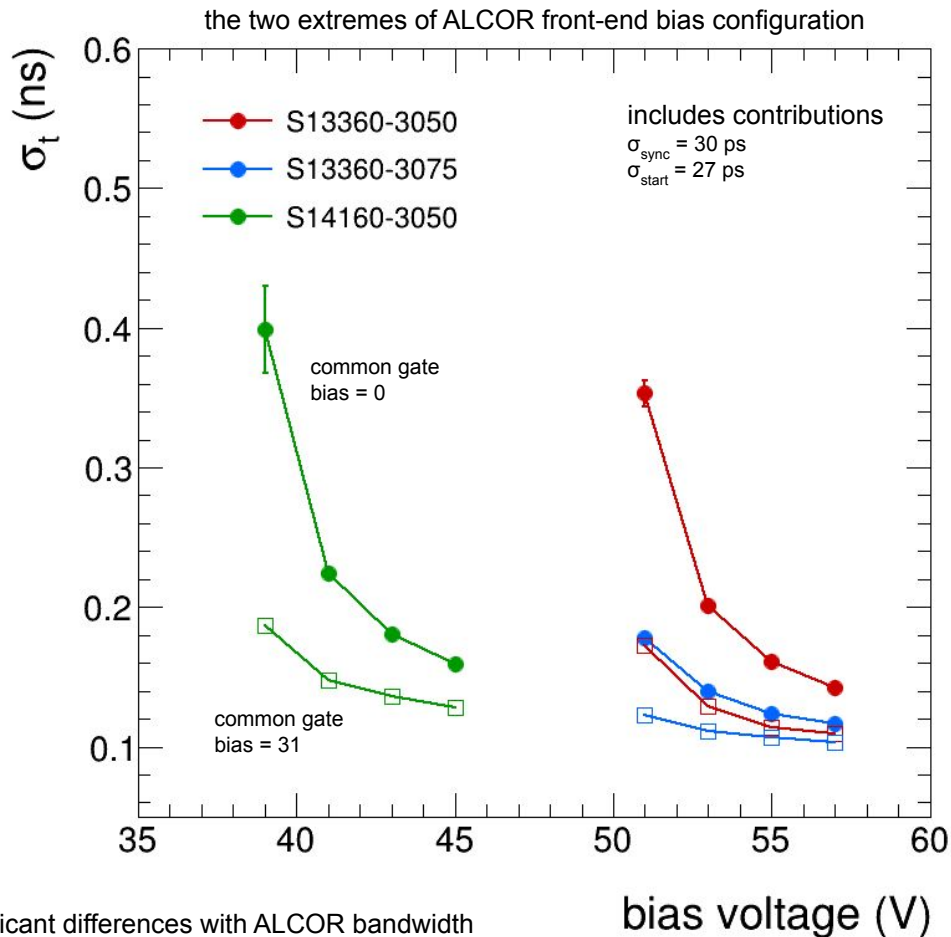
- to measure laser pulse  $t_{\text{start}}$
- with 50 ps LSB TDC
- in synch with ALCOR readout

measure time coincidences  $\Delta t$  between reference and ALCOR reading SiPM



includes contribution for laser-ALCOR synchronization measured to be  $\sigma_{\text{sync}} = 30 \text{ ps}$  and reference time resolution measured to be  $\sigma_{\text{start}} = 27 \text{ ps}$

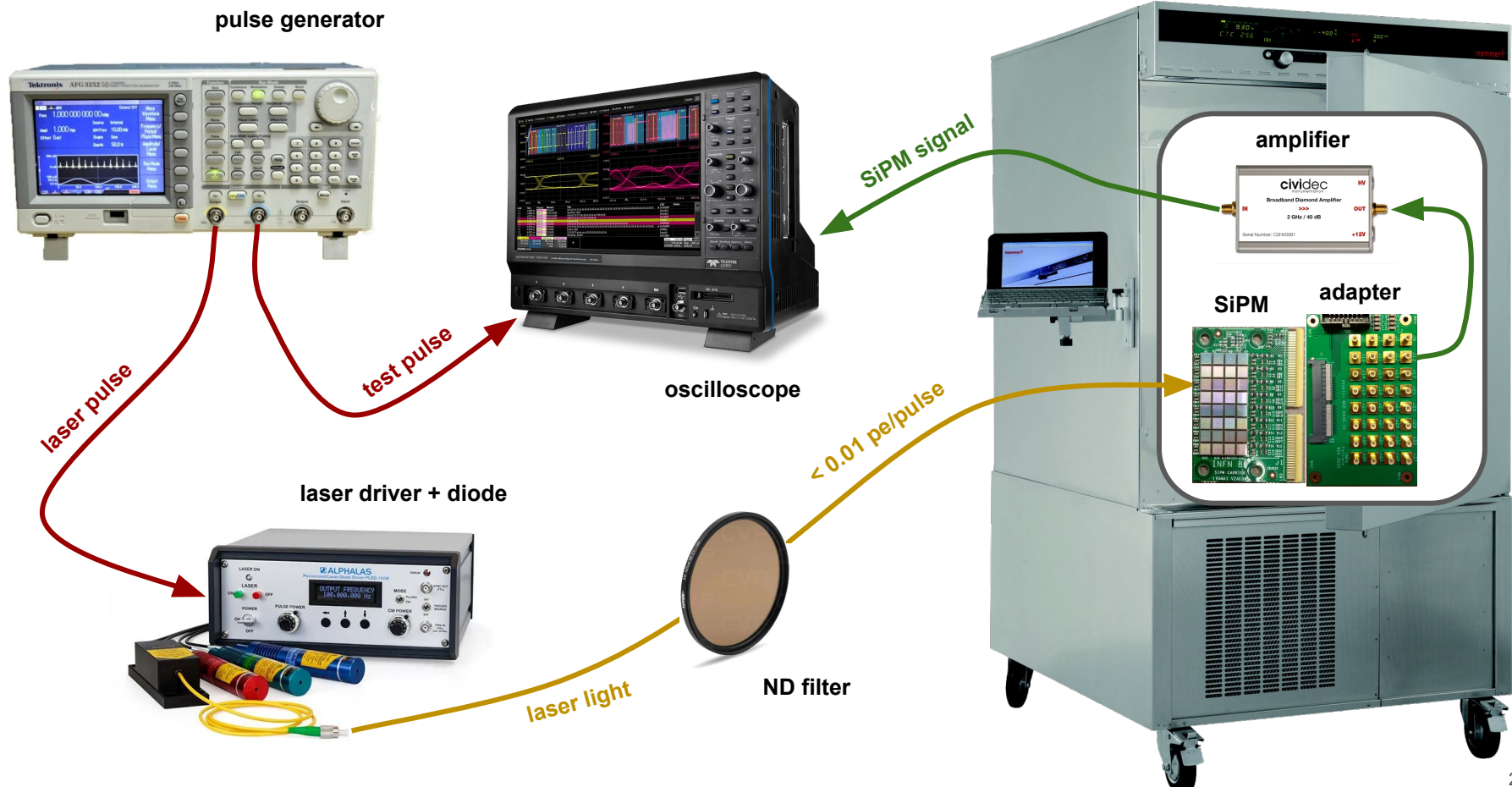
# Laser timing measurements with ALCOR



significant differences with ALCOR bandwidth

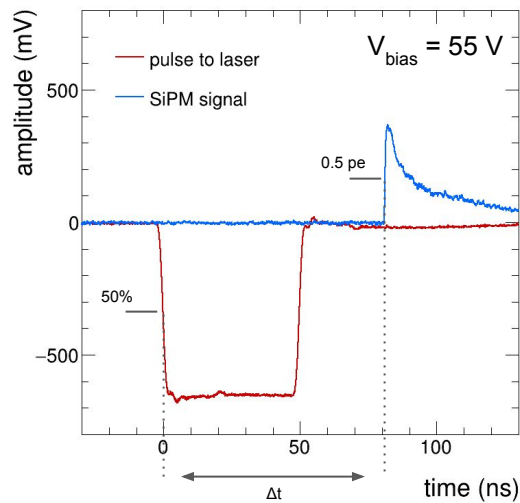
# Laser timing measurements with oscilloscope

climatic chamber

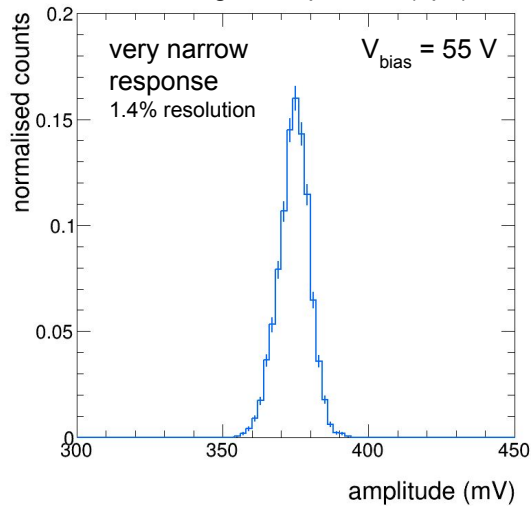


# Laser timing measurements with oscilloscope

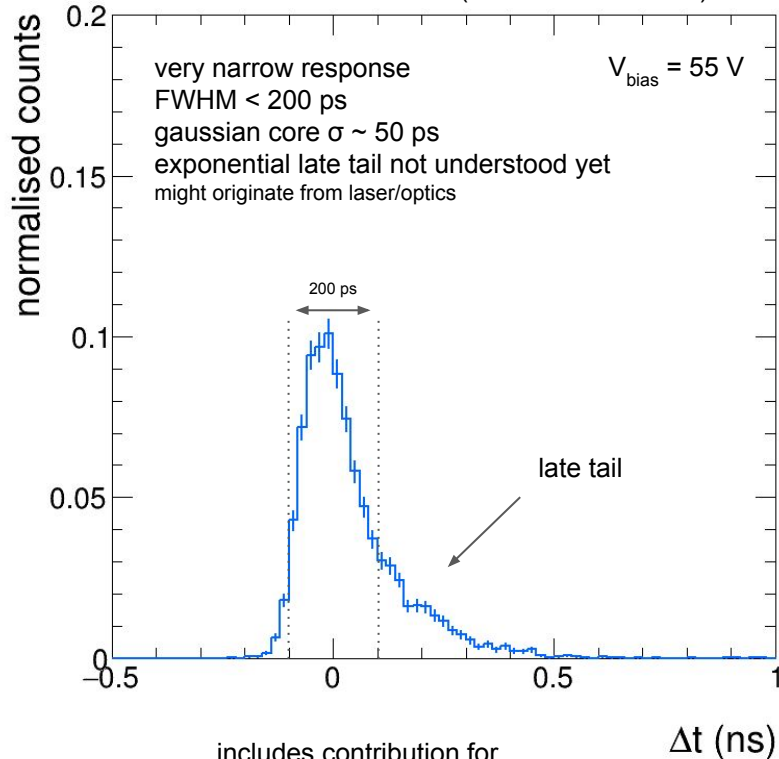
acquired oscilloscope traces



SiPM signal amplitudes (1pe)



laser-SiPM correlations (time-walk corrected)



measurements performed at  $T = -30 \text{ C}$  with

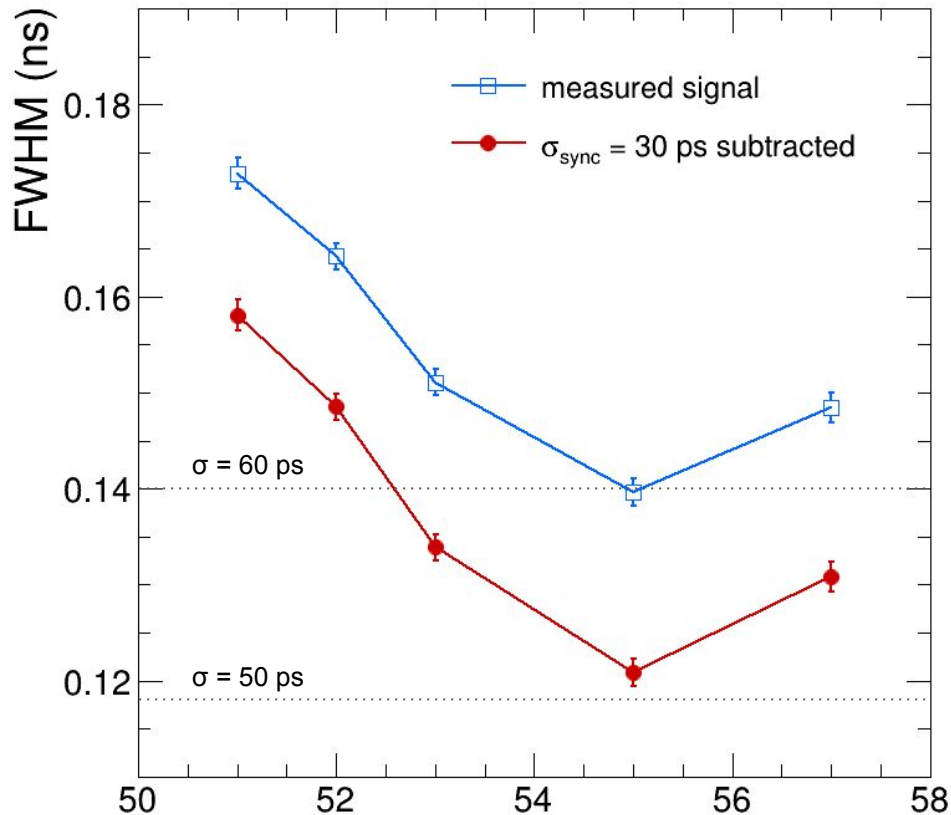
- Lecroy Waverunner 40186 oscilloscope
  - Cividec Broadband amplifier (40 db)
- timing defined with fixed thresholds
- laser pulse at 50% of signal
  - SiPM signal at 0.5 pe (average amplitude)

time-amplitude correlation (walk) corrected



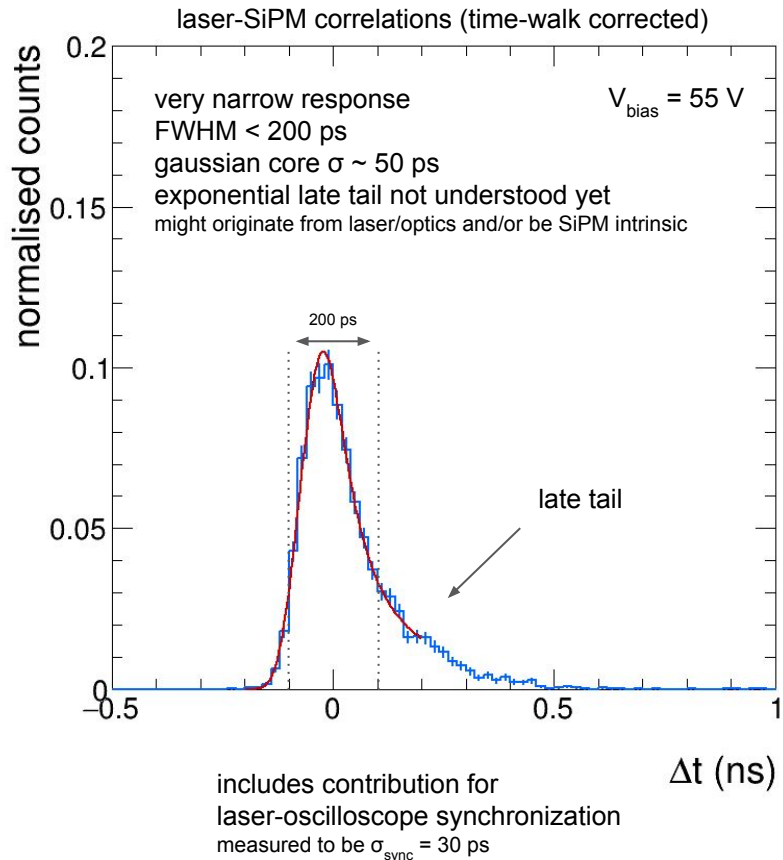
includes contribution for  
laser-oscilloscope synchronization  
measured to be  $\sigma_{\text{sync}} = 30 \text{ ps}$

# Laser timing measurements with oscilloscope



approaching  $\sigma_t = 50$  ps time resolution  
will soon measure effect of radiation damage on  $\sigma_t$

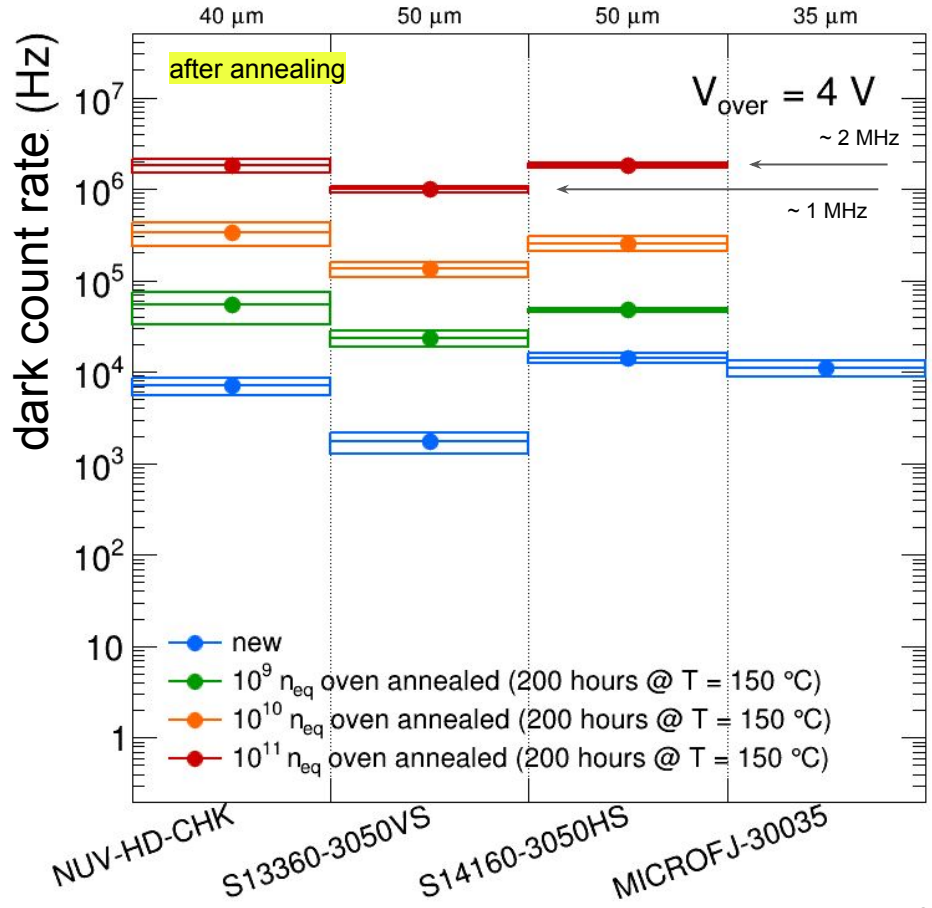
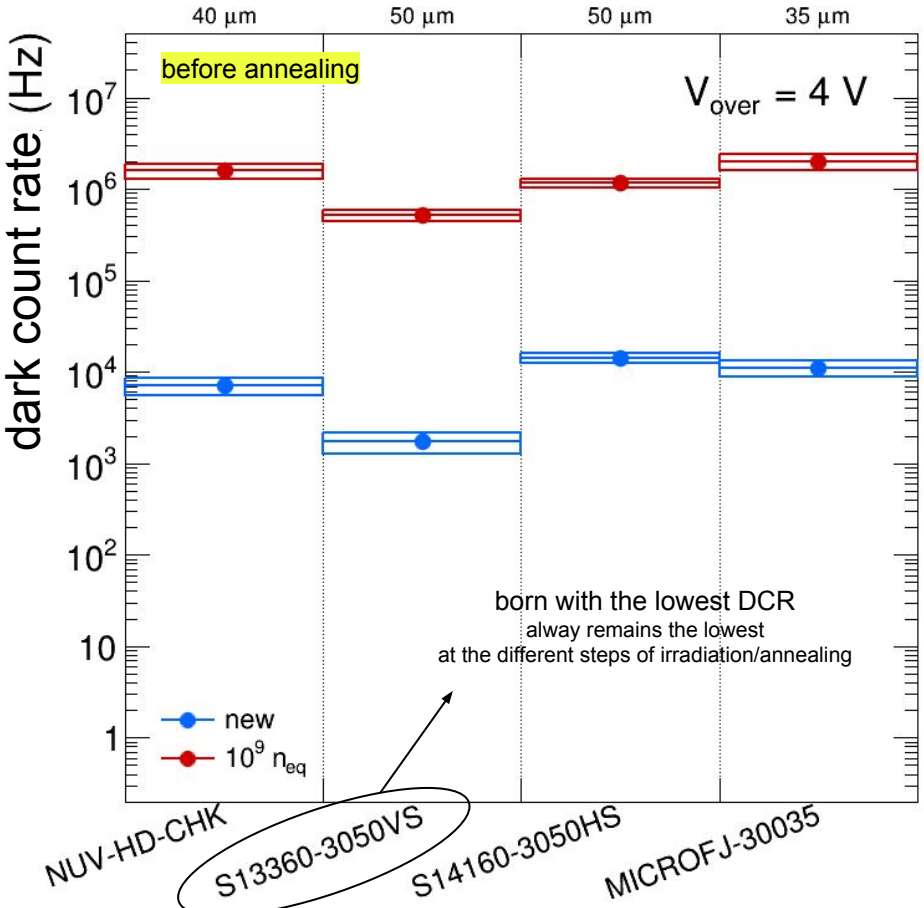
bias voltage (V)



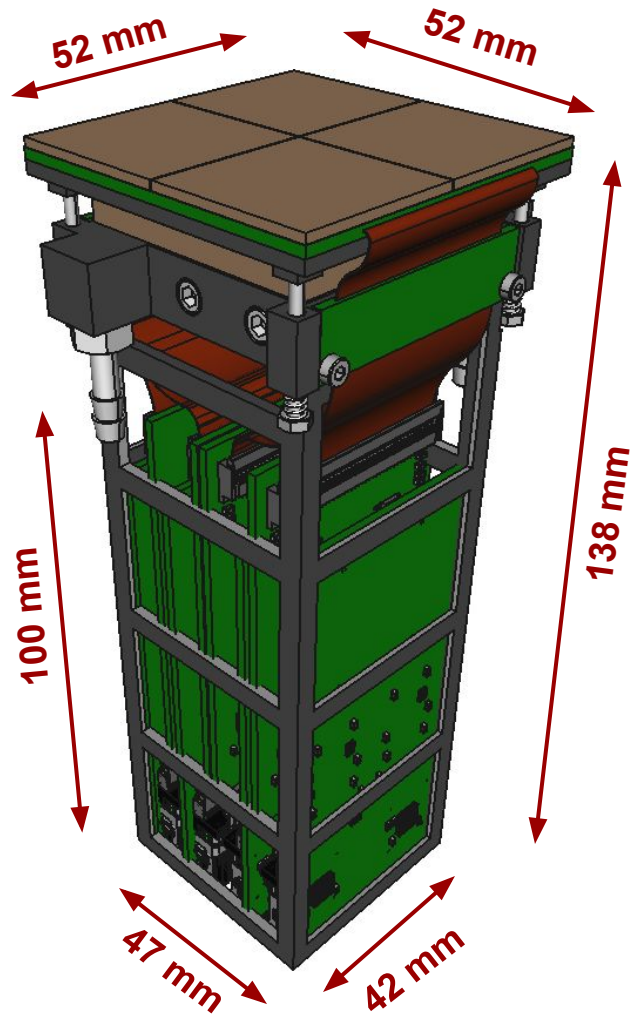
# Comparison between different sensors

comparison at same Vover not totally fair

important to consider PDE (and SPTR) → SNR ~ PDE / DCR  
 unlikely 2x larger DCR is matched by 2x larger PDE









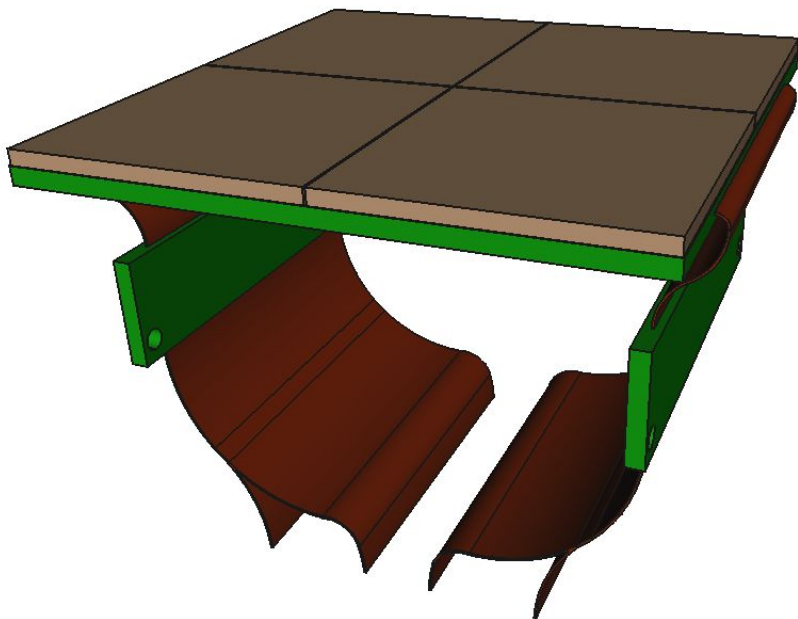
# Carrier board V2

mounts 4x SiPM sensor matrices (256 total channels)

receives HV and sends signals via flex connectors (1 mm bending radius)

PCB-flex-PCB-flex design to host HV RC-filters

back-side temperature sensors for monitor / feedback



project completed  
boards received

**designed in Bologna**

**Casimiro Baldanza**

# Adapter board and MasterLogic V2

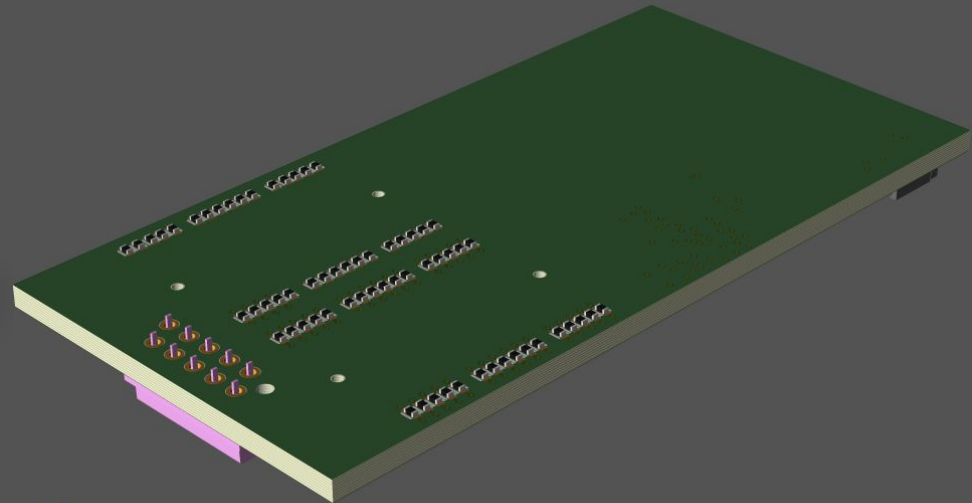
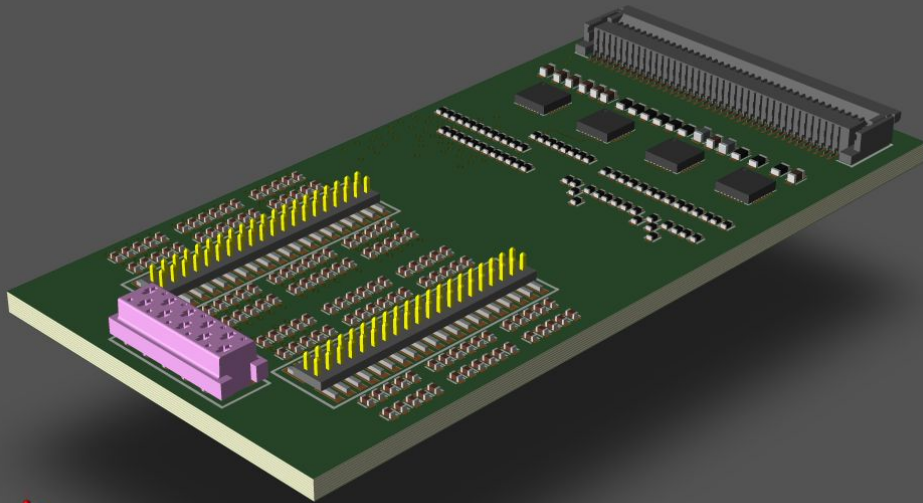
receives signals from SiPM, ships them to ALCOR  
includes **complex circuitry** to

- allow HV regulation
  - 0-5 V for each channel
  - 0-80 V for groups of 8 channels
- derivate signals before ALCOR
- switch from “regular mode” to “annealing mode”

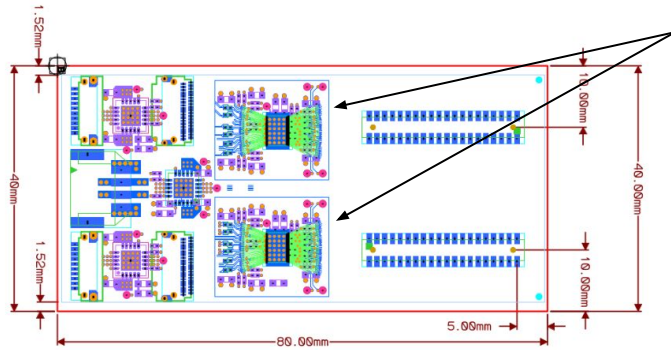


project completed  
boards received

**designed in Ferrara**  
**Roberto Malaguti**



# ALCOR board V2

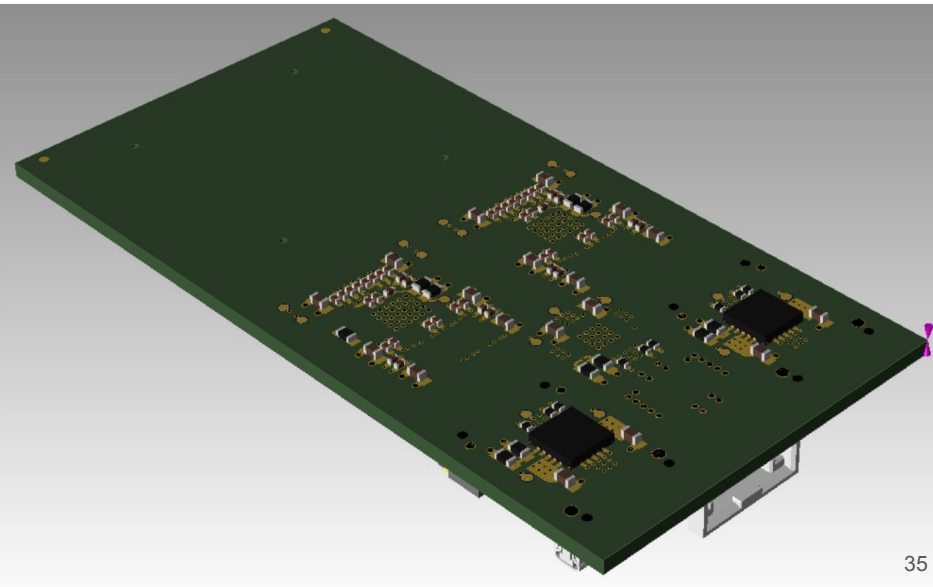
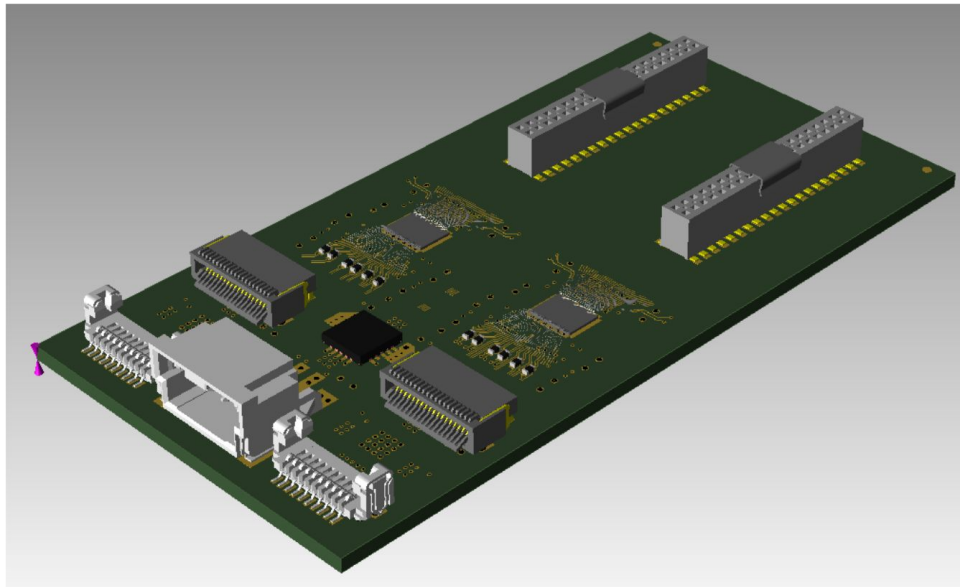


2x ALCOR-v2 ASICs (2x 32 channels)  
future ALCOR-v3 will be 64 channels

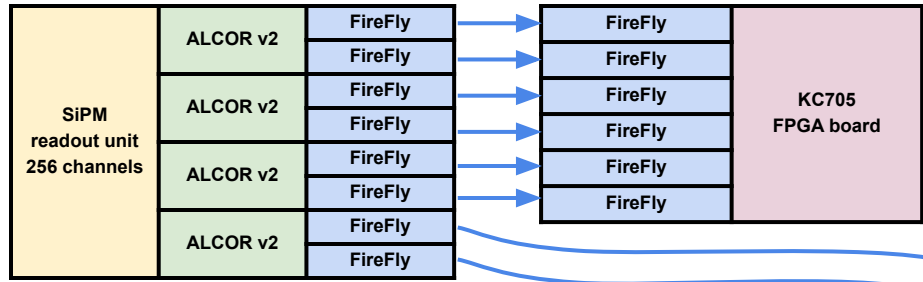


project completed  
boards received

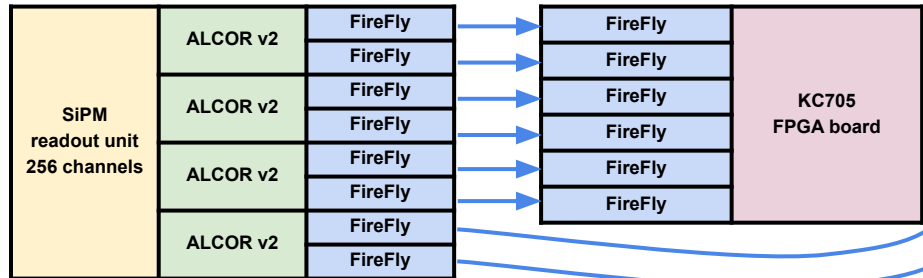
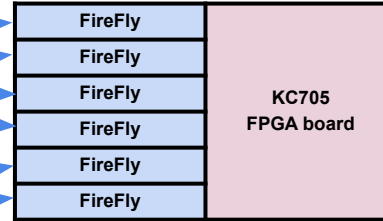
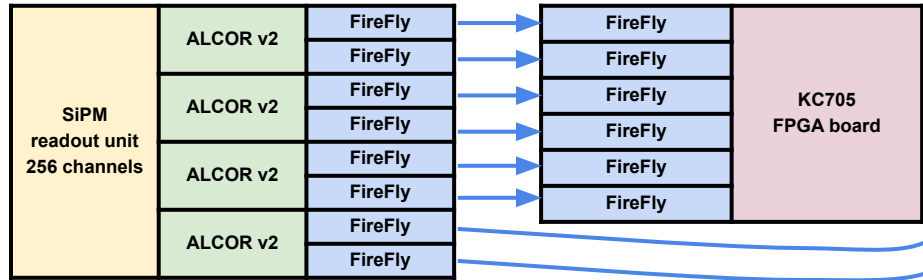
**designed in Torino**  
**Marco Mignone**



# prototype readout in 2023



readout of photodetector units  
in 2023 beam test will be done  
with **KC705 commercial boards**  
Xilinx Kintex 5 FPGA evaluation boards



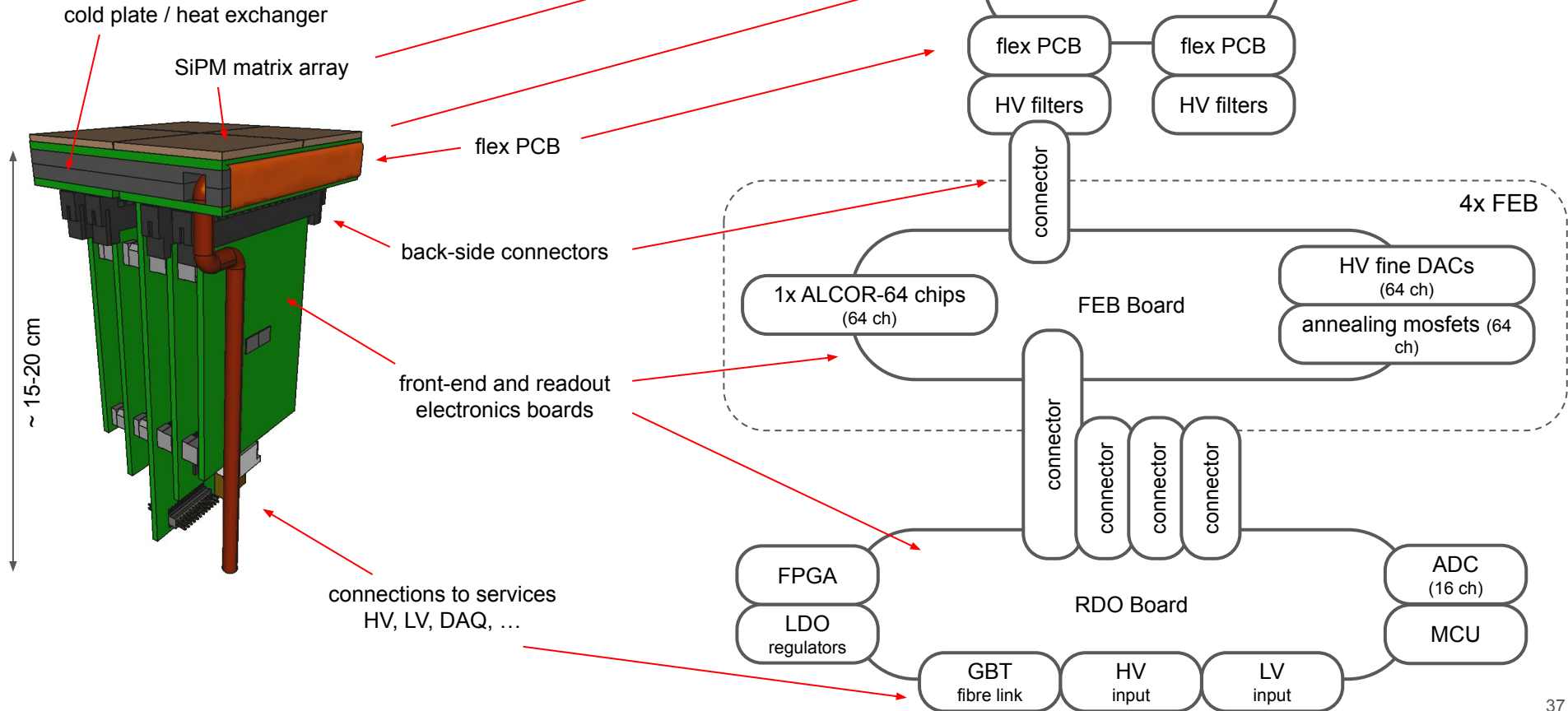
**time to start developing custom readout boards for 2024 beam tests and TDR**

2024: design and develop EIC-driven readout boards (RDO)

- close to the final RDO design and PDU layout
- with the capability to also serve current electronics

# PDU electronics

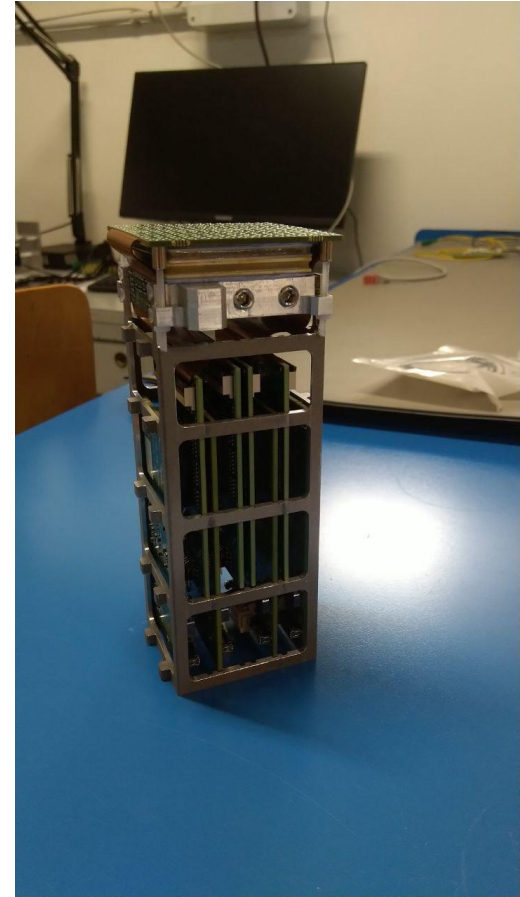
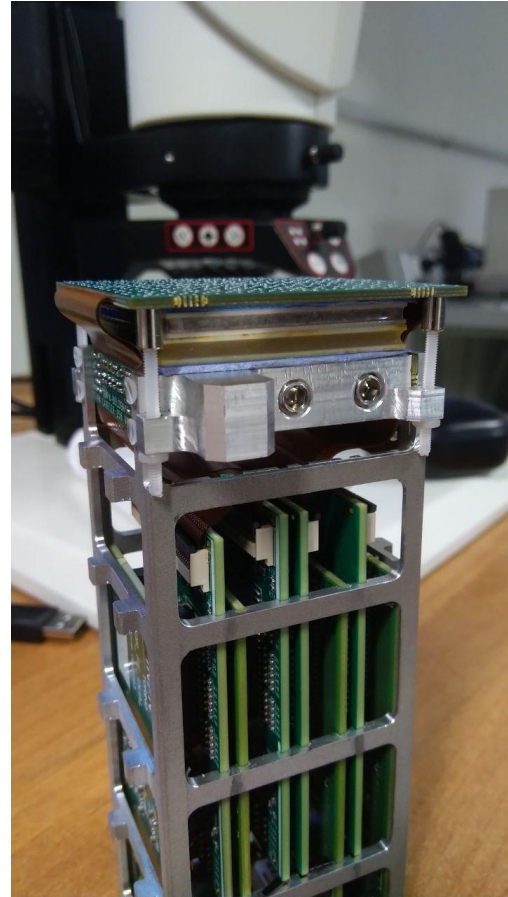
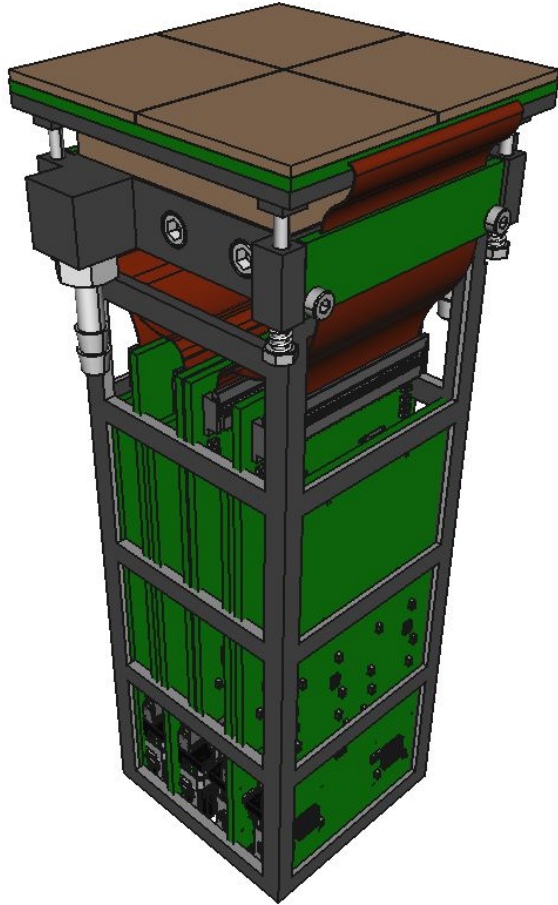
## conceptual design of final layout





# From design to assembly

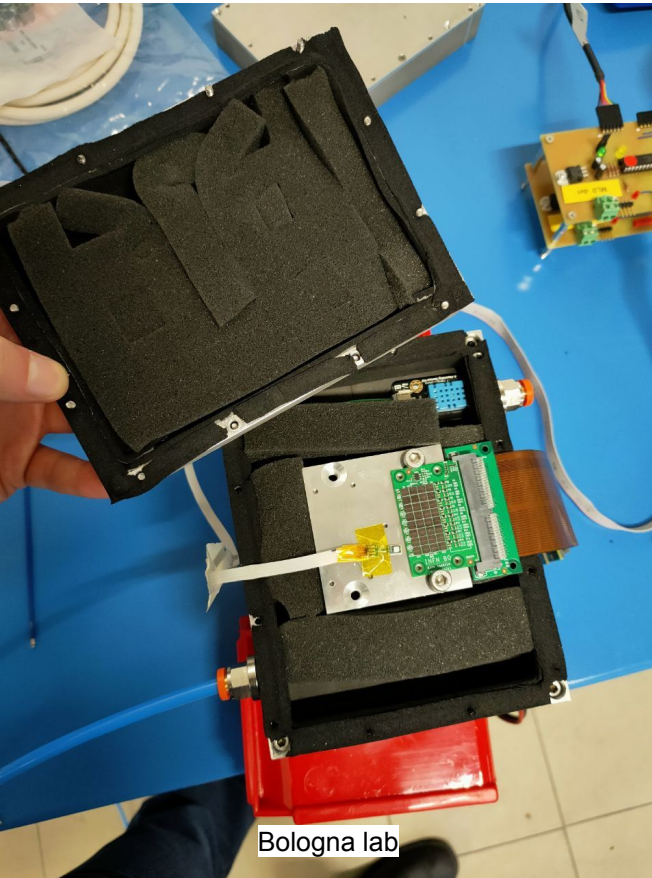
dummy assembly tests with empty SiPM carriers  
to check mechanical tolerances and get confidence with  
new electronics (come in lab to see the real piece)



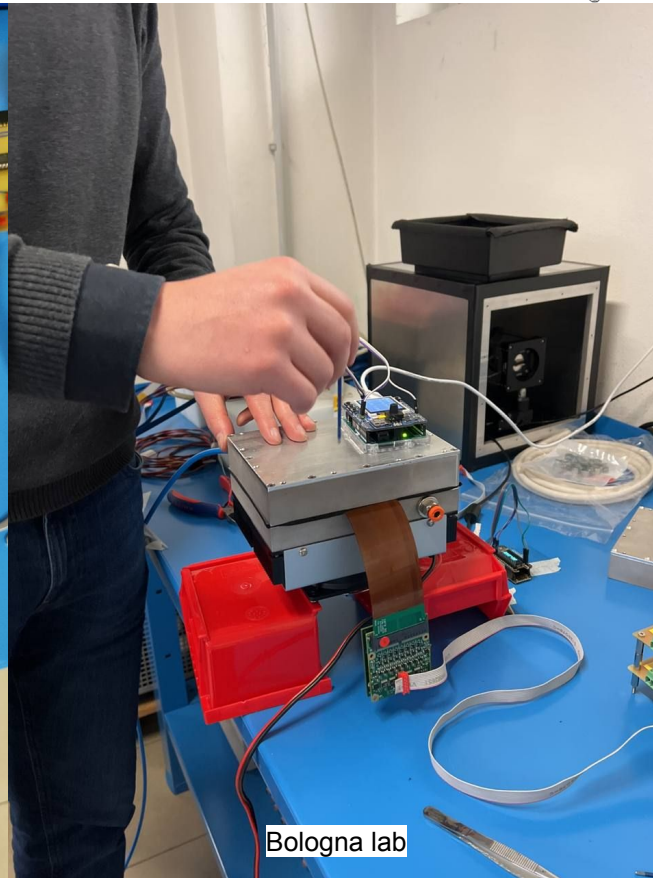


# Air-cooled portable Peltier box

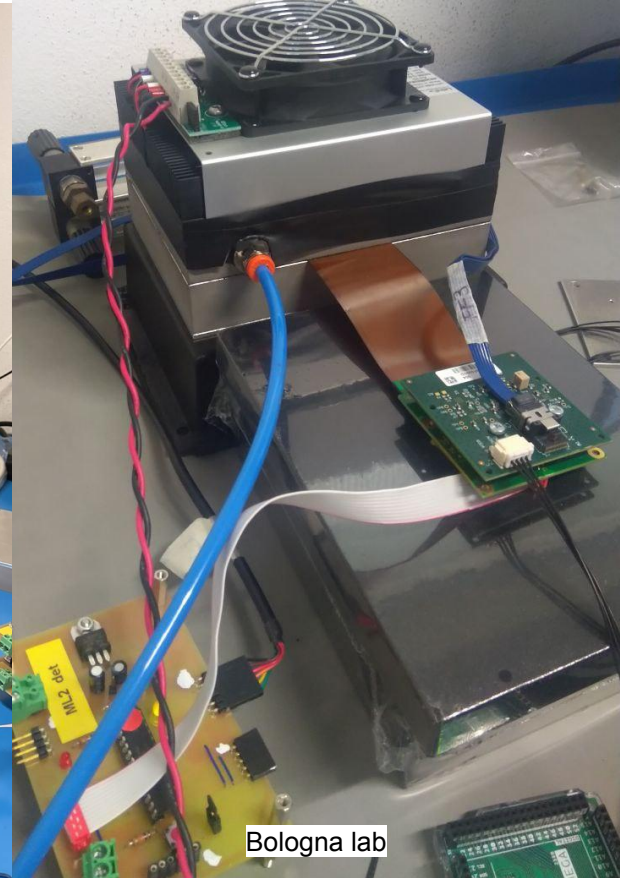
designed and realised by us based on Laird cooler assembly



Bologna lab

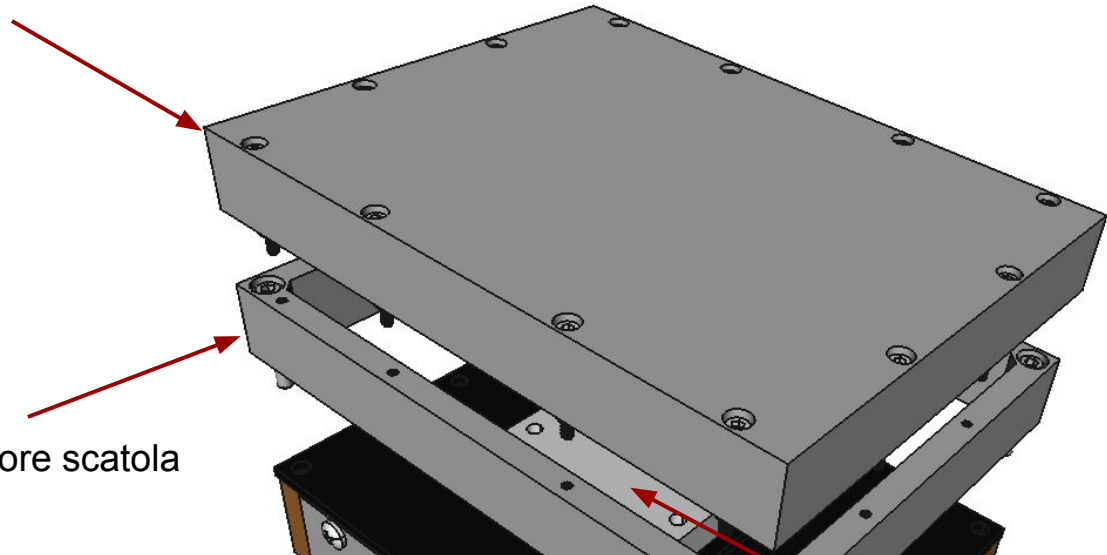


Bologna lab



Bologna lab

coperchio scatola



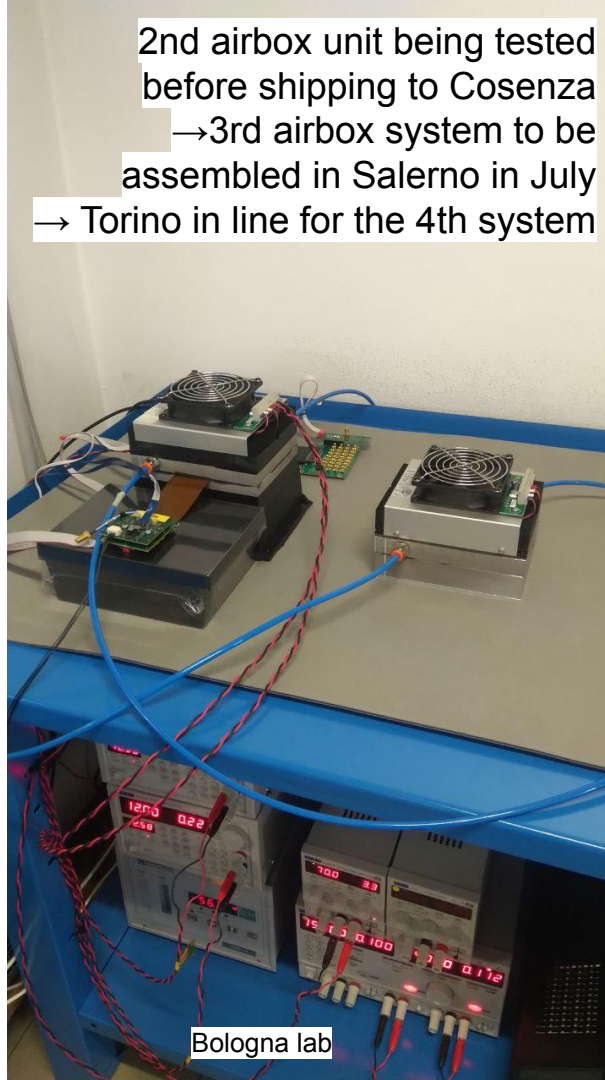
parte inferiore scatola

modulo raffreddamento  
ad aria Peltier

piastra di adattamento

# airbox in Cosenza

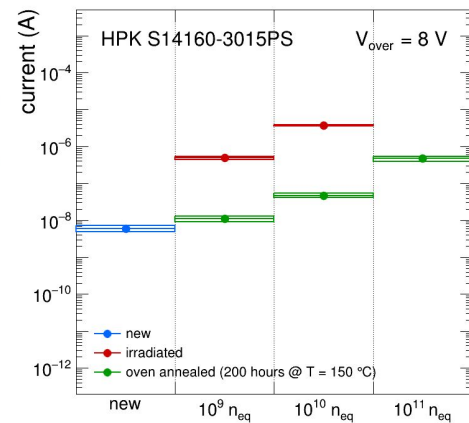
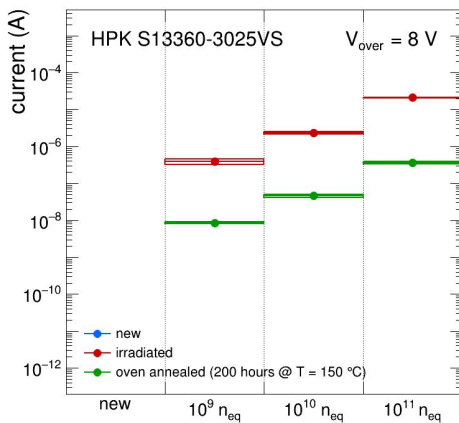
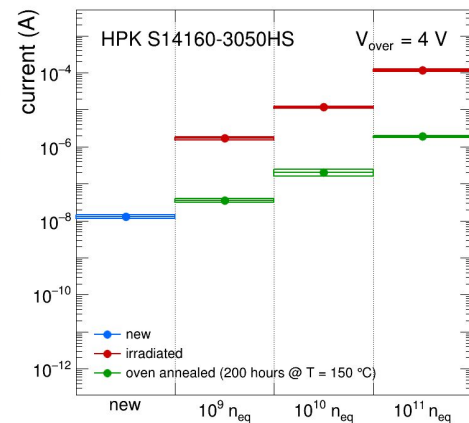
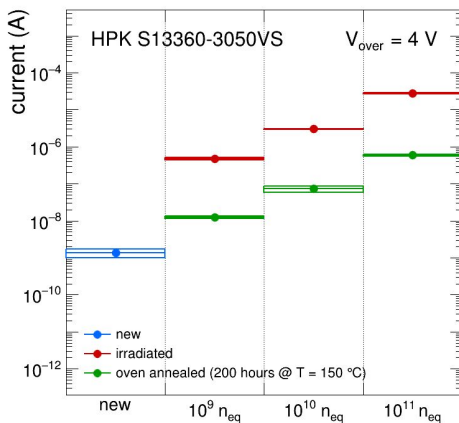
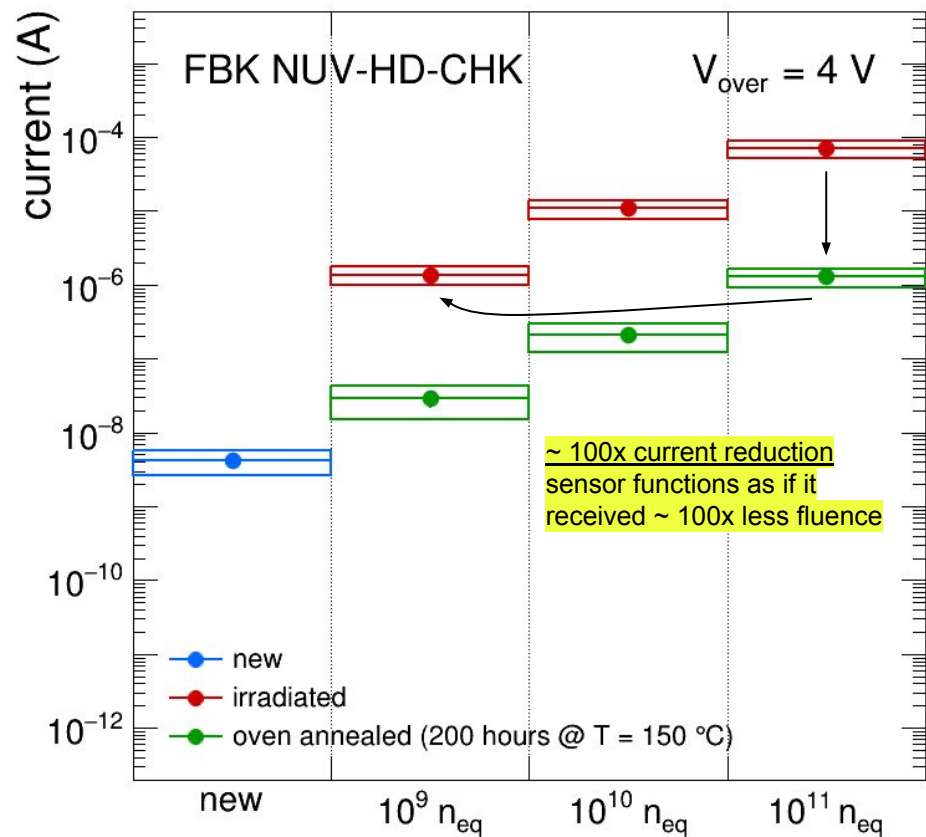
- **airbox installed in Cosenza**
  - after tests in Bologna
  - shipped to Cosenza
  - system installed on 13-14 April
  - good teamwork
    - Bologna
    - Cosenza
    - Salerno
- **Cosenza ready to contribute**
  - to SiPM characterisation
  - in charge of proton-energy scan
- **3rd airbox to Salerno**
  - system will be installed in July
  - increase SiPM test capacity
- **Torino in line for 4th system**
  - for tests of ALCOR chip with SiPM at low T





# High-temperature annealing recovery

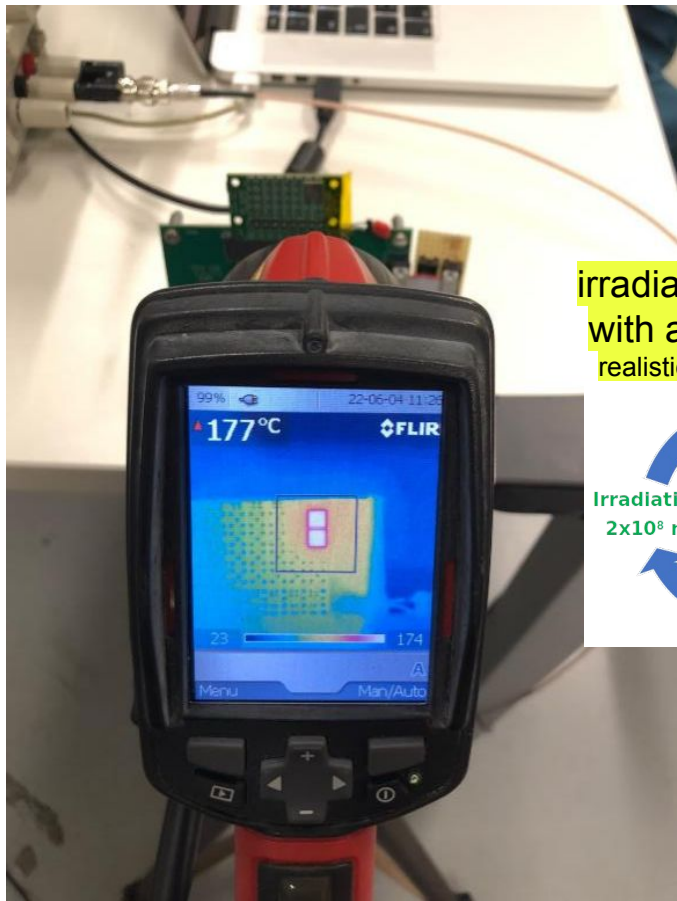
oven annealing  
~ 1 week at 150 C



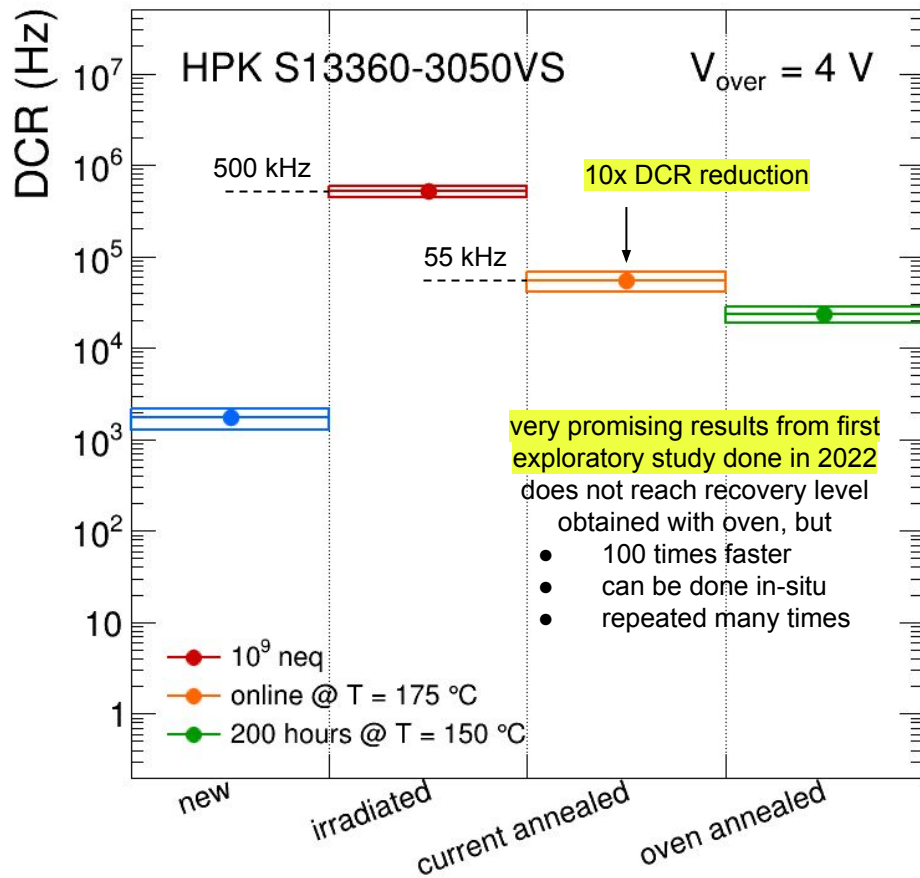
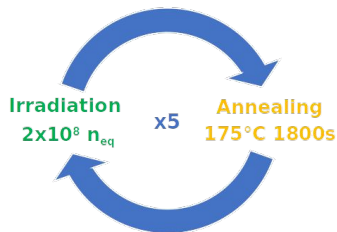
similar observation with various types of Hamamatsu sensors

# “Online” self-induced annealing

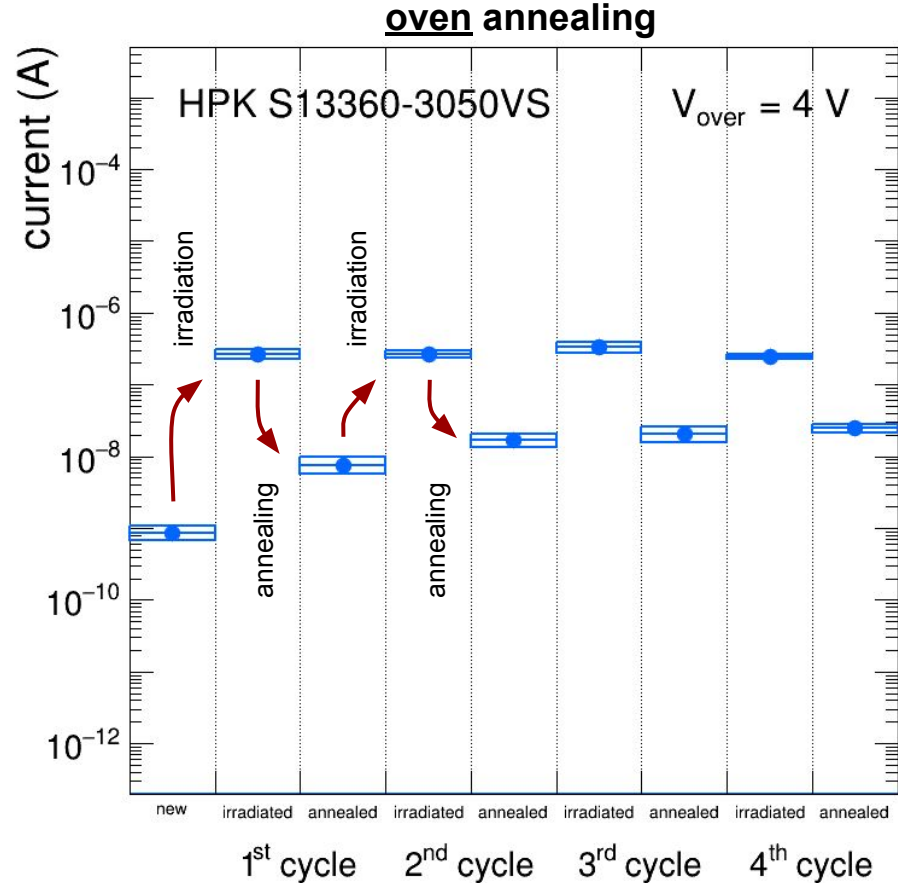
studies for “in-situ” SiPM recovery  
 multiple cycles: 30 minutes at 175 C  
 ~ 1 W power/sensor delivered with forward bias voltage



irradiation interleaved  
 with annealing cycle  
 realistic experimental case



# Repeated irradiation-annealing cycles



## test reproducibility of repeated irradiation-annealing cycles

simulate a realistic experimental situation

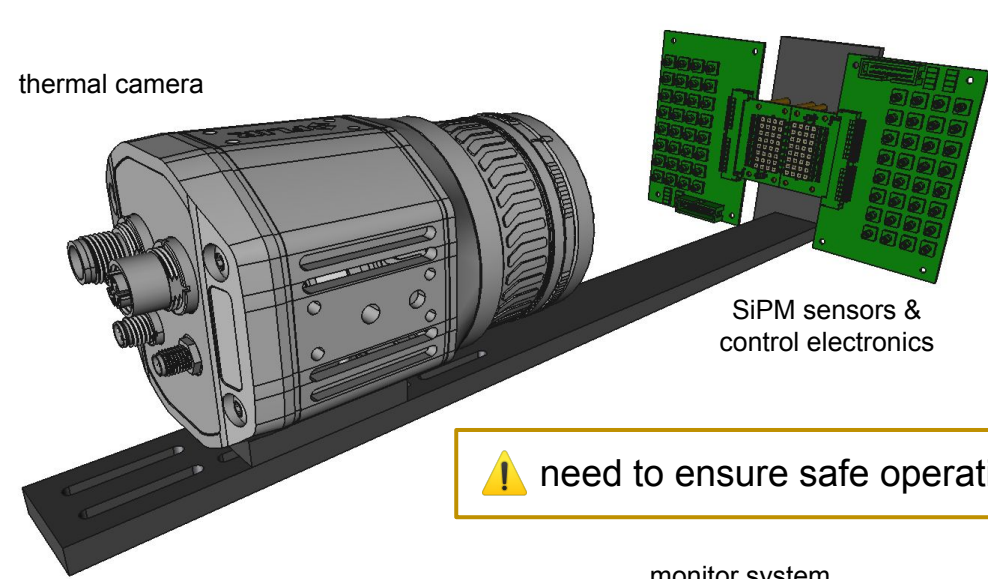
- consistent irradiation damage
  - DCR increases by  $\sim 500 \text{ kHz}$  (@  $V_{\text{over}} = 4$ )
  - after each shot of  $10^9 n_{\text{eq}}$
- consistent residual damage
  - $\sim 15 \text{ kHz}$  (@  $V_{\text{over}} = 4$ ) of residual DCR
  - builds up after each irradiation-annealing

## annealing cures same fraction of newly-produced damage

$\sim 97\%$  for HPK S13360-3050 sensors



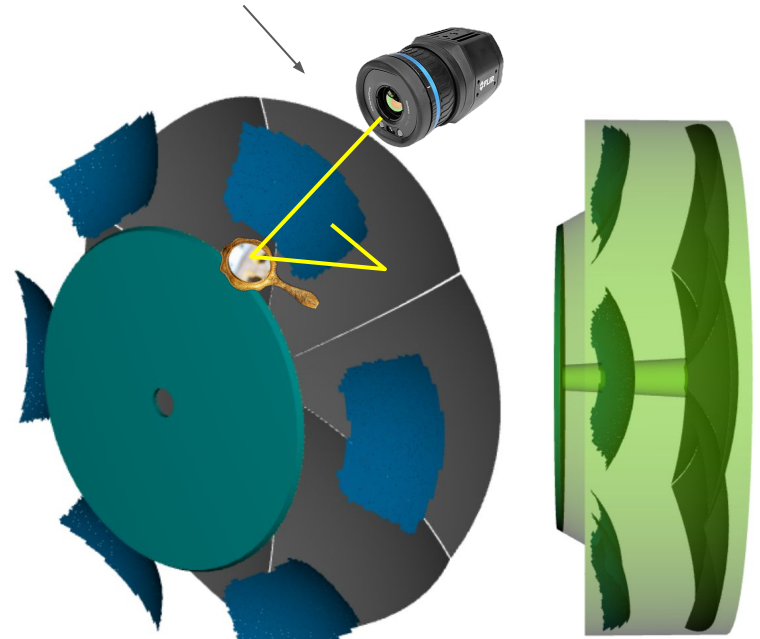
# Automated multiple SiPM online self-annealing



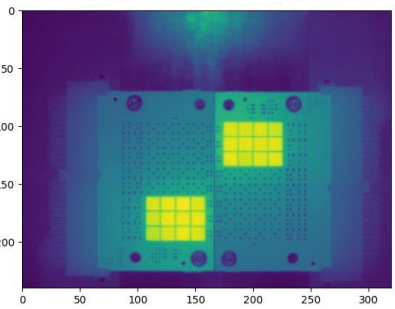
demonstrator system for online temperature monitor and control of each individual SiPM

technical feasibility and implementation in the experimental environment to be studied in details

! need to ensure safe operation



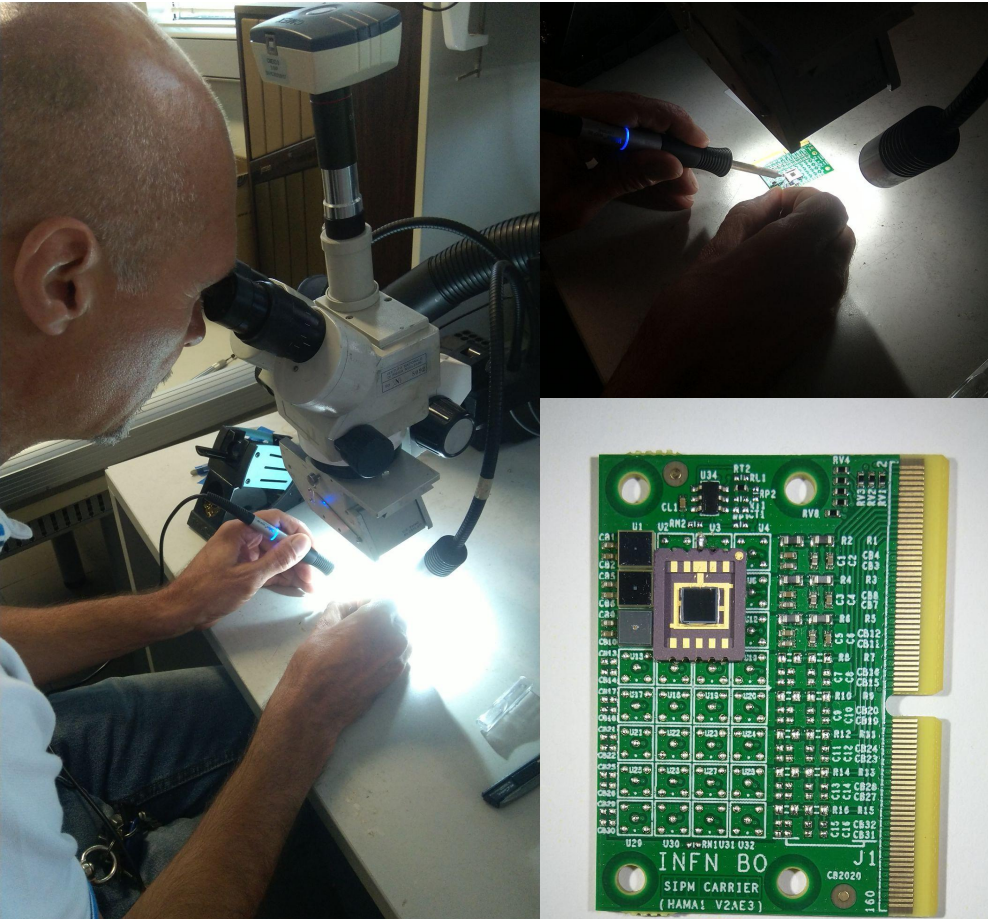
thermal image



monitor system



# New Hamamatsu SiPM prototypes



S13360-3050UVE

## newly-developed Hamamatsu SiPM sensors

based on S13360 series

few samples of 50  $\mu\text{m}$  and 75  $\mu\text{m}$  SPAD sensors

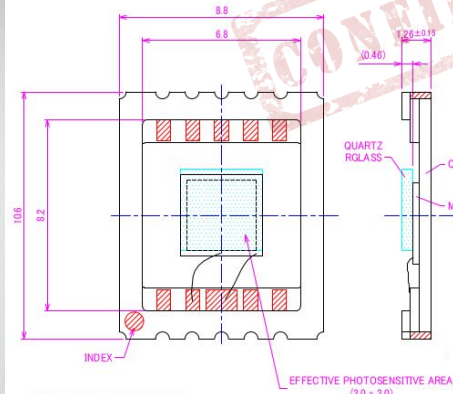
### on paper they look VERY promising

- improved NUV sensitivity
- improved signal shape
- improved recharge time

mounted on EIC SiPM test boards

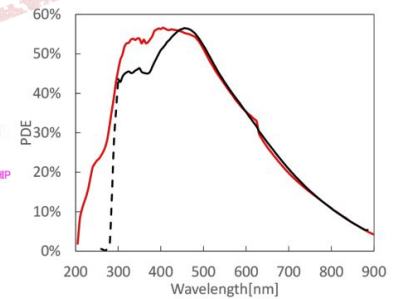
we will characterise and test them in full

irradiation, annealing, laser, ...



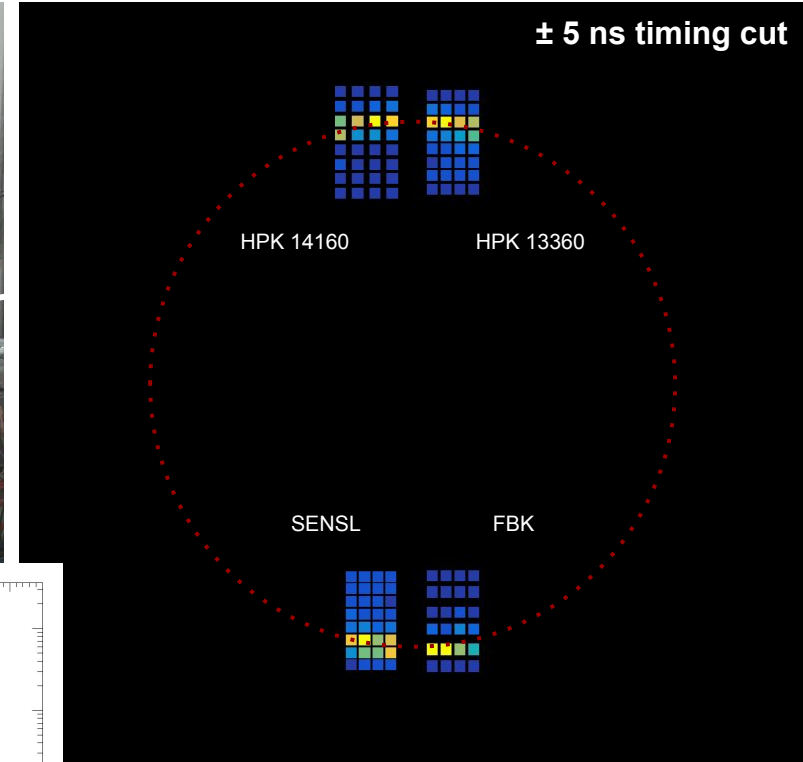
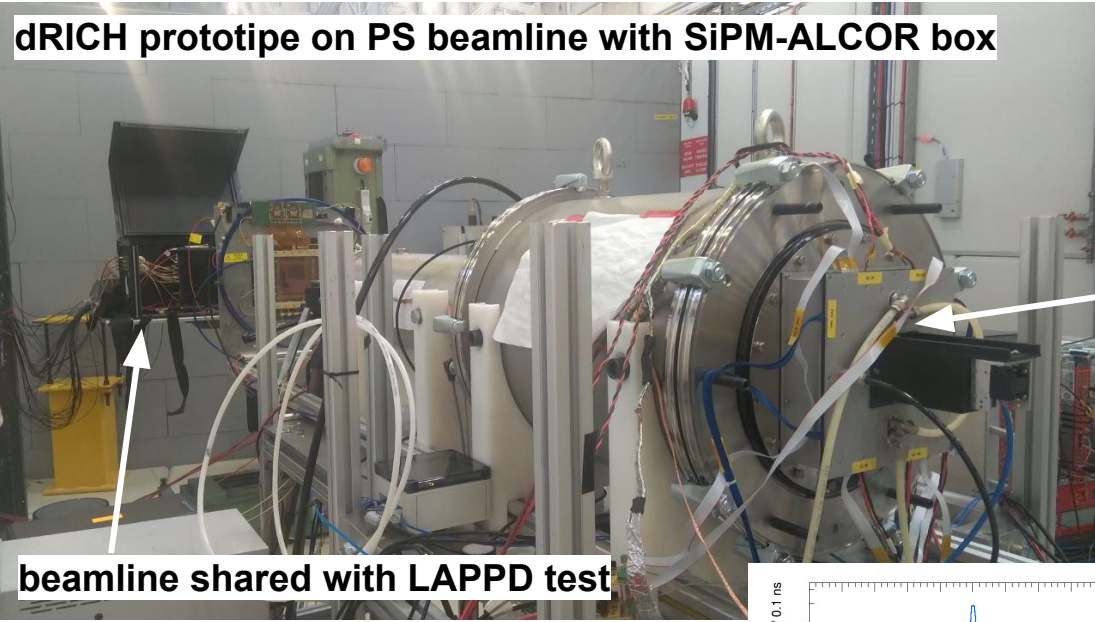
• GENERAL TOLERANCE:  $\pm 0.3\text{mm}$   
 •  $A_2$ -WIRES ARE NOT PROTECTED.

CONFIDENTIAL



— Prototype : based on S13360 series (75 $\mu\text{m}$ )  
 — Conventional : S14520 series (75 $\mu\text{m}$ )

# 2022 test beam at CERN-PS



8 GeV negative beam (aerogel rings)

**successful operation of SiPM**  
irradiated (with protons up to  $10^{10}$ )  
 and annealed (in oven at 150 C)

